

Complex Thermoelectric Materials

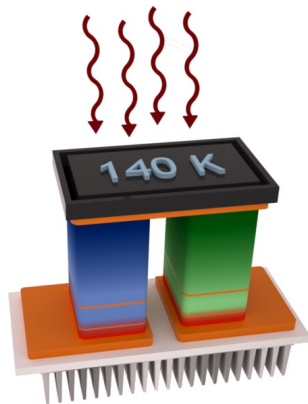
G. Jeffrey Snyder

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Evanston IL, USA

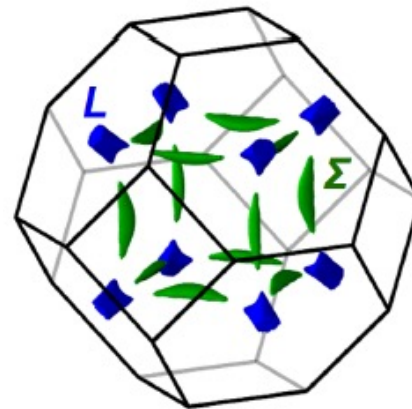
<http://thermoelectrics.matsci.northwestern.edu>

Device Engineering



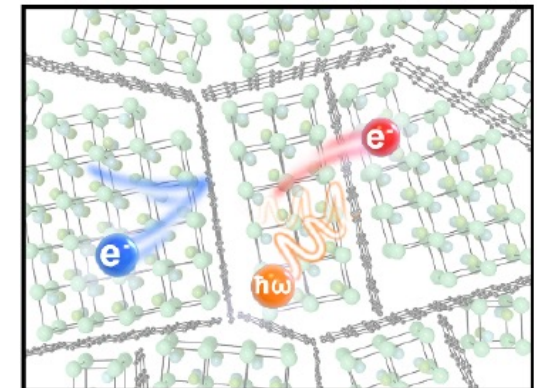
Compatibility

Electron-Phonon Engr.



Complex Structures

Interfaces



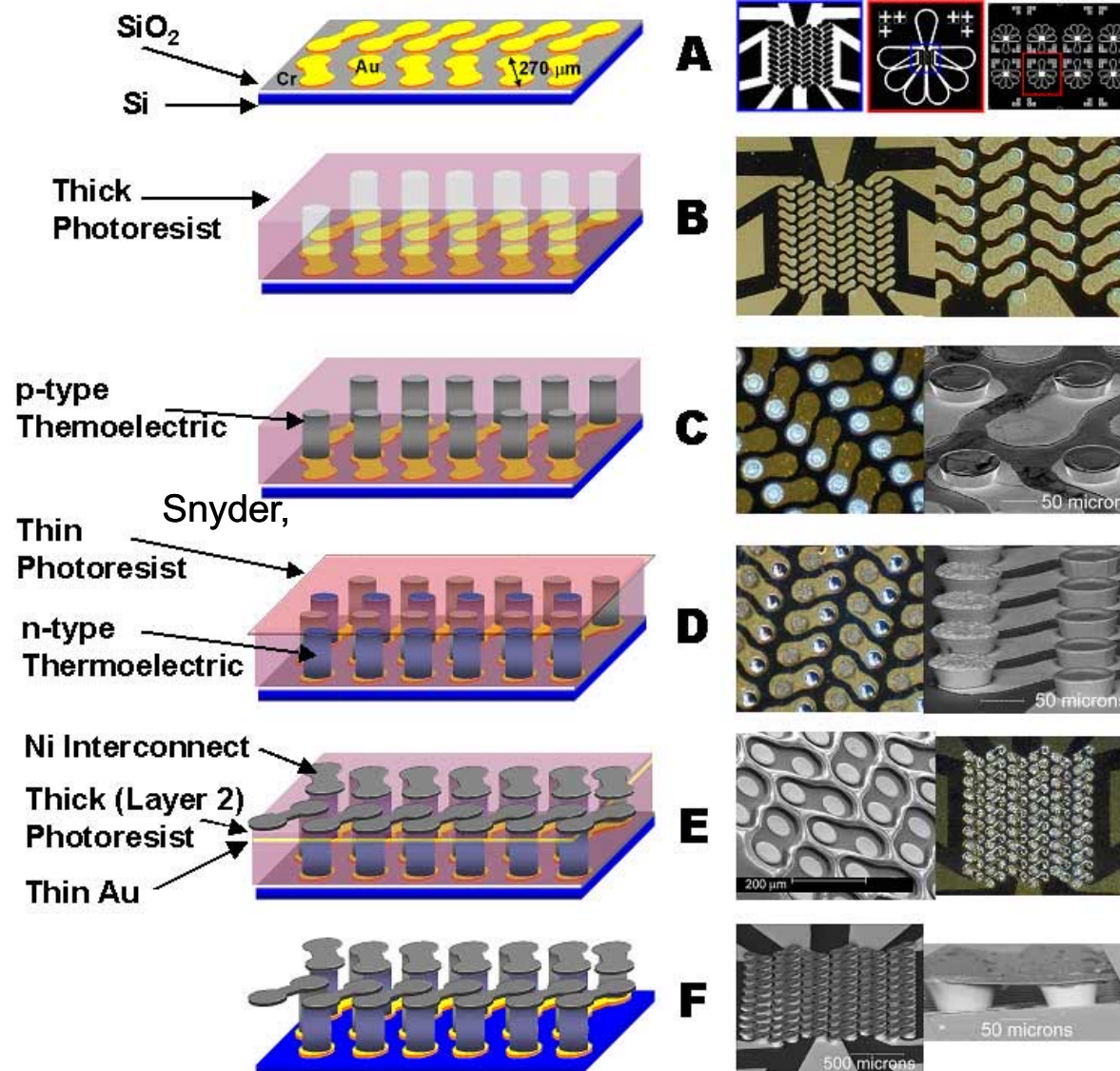
Microstructures

JPL 1997-2006



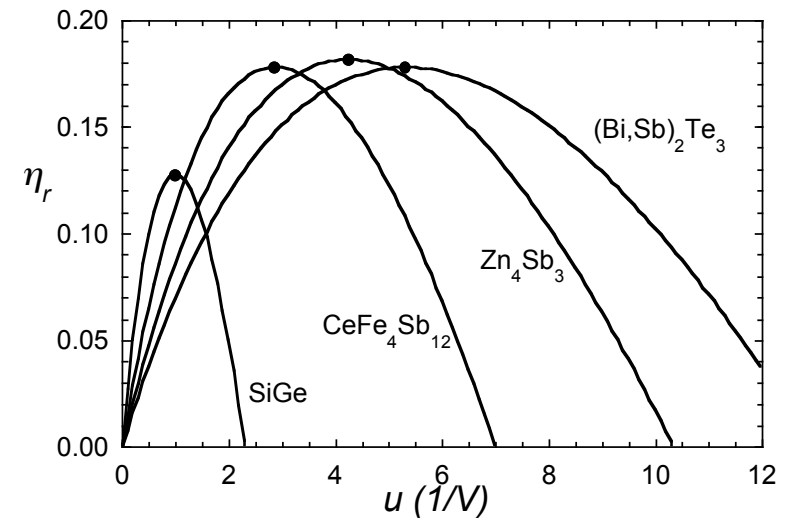
Thermoelectrics
Caltech Materials Science

Electrochemical MEMS MicroDevice

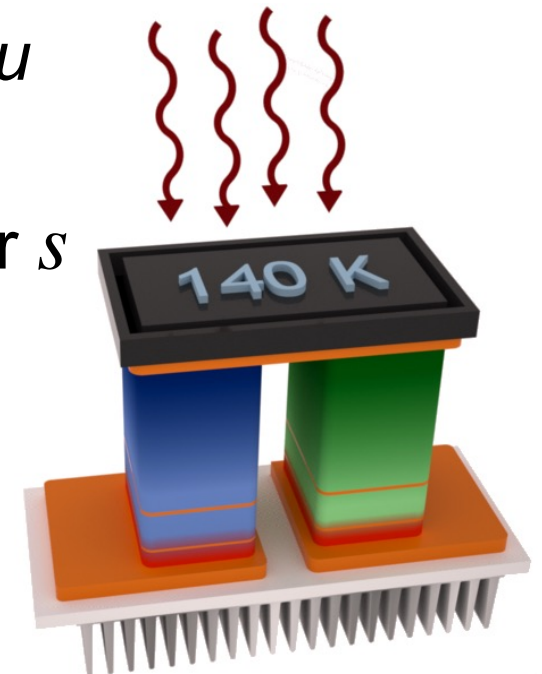


Compatibility Factor

$$s_g = \frac{\sqrt{1 + zT} - 1}{\alpha T}$$



- Power and efficiency depend on red. current u
 - not all T work at optimum efficiency
- Optimal reduced current is compatibility factor s
- s depends on material properties
- Leads to Thomson Cooler



ZT Calculator

Materials figure of merit

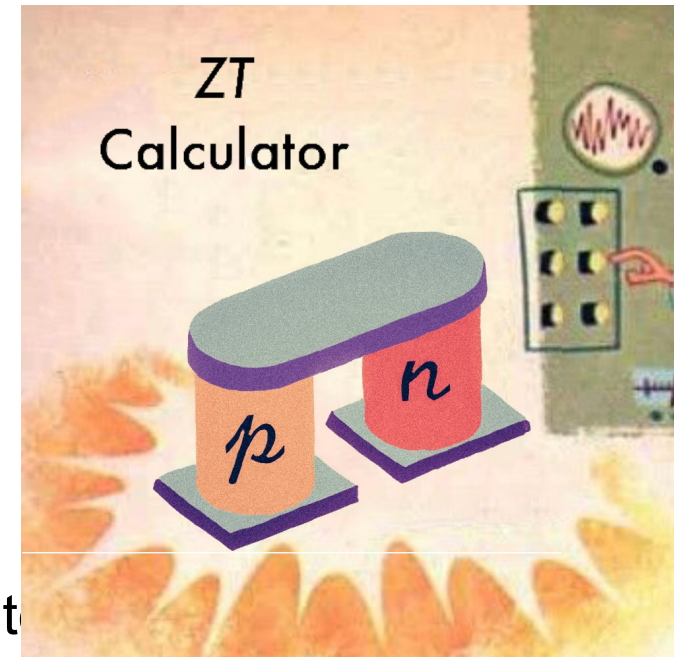
$$zT = \frac{S^2}{\rho \kappa} T$$

Efficiency comes from device ZT

$$\eta = \frac{\Delta T}{T_h} \cdot \frac{\sqrt{1 + ZT} - 1}{\sqrt{1 + ZT} + T_c/T_h}$$

Exact definition of ZT

Can be calculated from spreadsheet calculator easy!



T (K)	Seebeck (μV/K)	resistivity (10 ⁻³ Ω cm)	thermal cond. (W/m K)	zT	max Red eff	s (1/V)	u (1/V)	Red eff	Φ (V)	efficiency	ZT
300	106	0.71	2.52	0.19	4.3%	2.83	2.7815	4.3%	0.391		
325	119	0.75	2.29	0.27	5.9%	3.26	2.8222	5.8%	0.393	0.4%	0.22
350	131	0.81	2.09	0.36	7.6%	3.58	2.8658	7.3%	0.395	0.9%	0.26
375	142	0.90	1.94	0.43	8.9%	3.70	2.9084	8.6%	0.397	1.4%	0.30
400	154	1.01	1.79	0.52	10.4%	3.79	2.9596	10.0%	0.399	2.0%	0.33
425	166	1.14	1.68	0.61	11.8%	3.81	3.0174	11.4%	0.402	2.7%	0.37
450	178	1.28	1.57	0.71	13.3%	3.84	3.0804	12.9%	0.405	3.3%	0.40
475	191	1.43	1.49	0.81	14.8%	3.83	3.1537	14.4%	0.408	4.0%	0.44
500	205	1.59	1.40	0.95	16.5%	3.86	3.2418	16.2%	0.411	4.8%	0.48
525	219	1.74	1.33	1.08	18.2%	3.87	3.3365	17.9%	0.414	5.6%	0.53
550	229	1.90	1.26	1.21	19.6%	3.85	3.4259	19.4%	0.418	6.4%	0.57
575	239	2.06	1.21	1.31	20.6%	3.79	3.5132	20.6%	0.422	7.2%	0.62
600	247	2.22	1.16	1.42	21.7%	3.74	3.6039	21.7%	0.426	8.1%	0.66
625	254	2.37	1.13	1.50	22.5%	3.66	3.6893	22.5%	0.430	8.9%	0.71
650	258	2.52	1.09	1.58	23.2%	3.60	3.7663	23.2%	0.433	9.7%	0.75
675	262	2.66	1.07	1.63	23.7%	3.51	3.8429	23.6%	0.437	10.5%	0.79
700	266	2.80	1.04	1.70	24.3%	3.45	3.9254	24.1%	0.441	11.3%	0.83
725	269	2.94	1.03	1.74	24.7%	3.35	4.0046	24.1%	0.445	12.0%	0.87
750	269	3.08	1.02	1.73	24.6%	3.23	4.0514	23.7%	0.448	12.8%	0.90
775	268	3.24	1.01	1.70	24.3%	3.10	4.0926	23.0%	0.452	13.4%	0.93
800	268	3.42	1.01	1.67	24.1%	2.95	4.1582	21.9%	0.455	14.0%	0.96

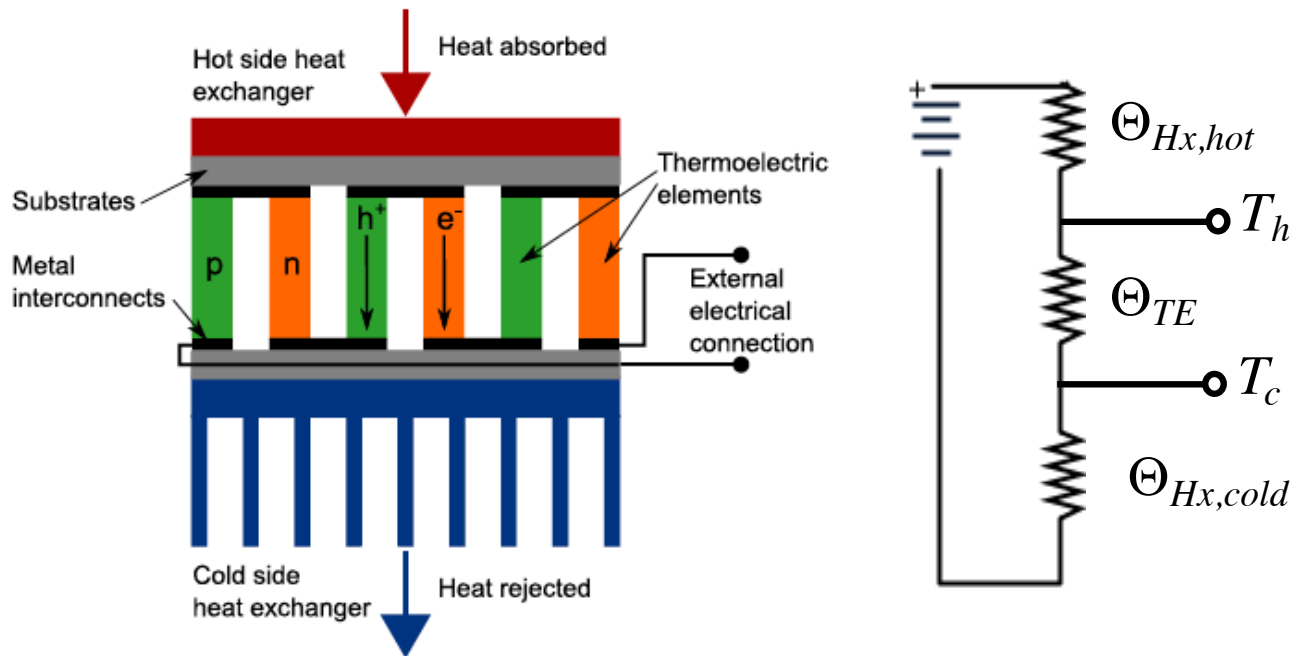
$$ZT = \left(\frac{T_h - T_c(1 - \eta)}{T_h(1 - \eta) - T_c} \right)^2 - 1$$



Leg Length from Thermal Impedance Match

Thermal Impedance match of Heat Exchanger
Effectively determines leg length of thermoelectric

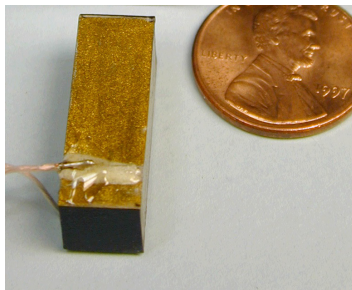
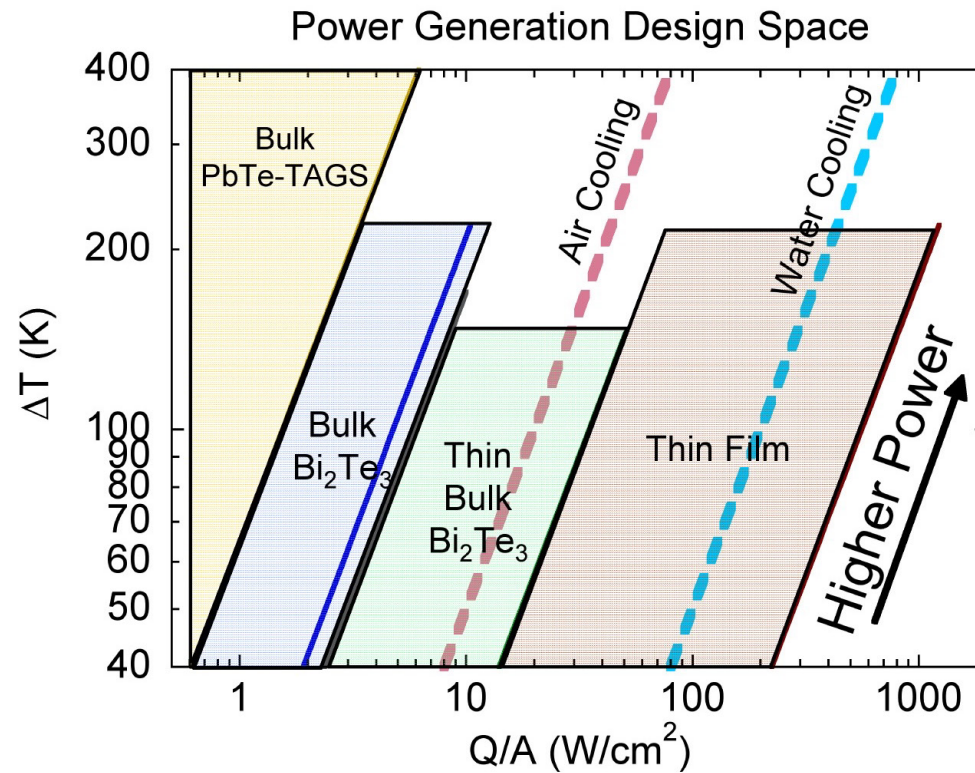
$$\Theta_{TE} = \Theta_{Hx}$$



$$\Theta_{TE} = \frac{l}{\kappa_{TE} A f}$$

l = leg length
 f = TE fill factor
 A = area

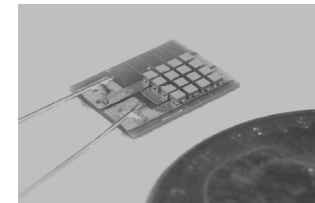
TE phase space



Thermopile
l ~ 20 mm



Commercial Module
l ~ 2 mm



Thin Film Device
l ~ 0.02 mm

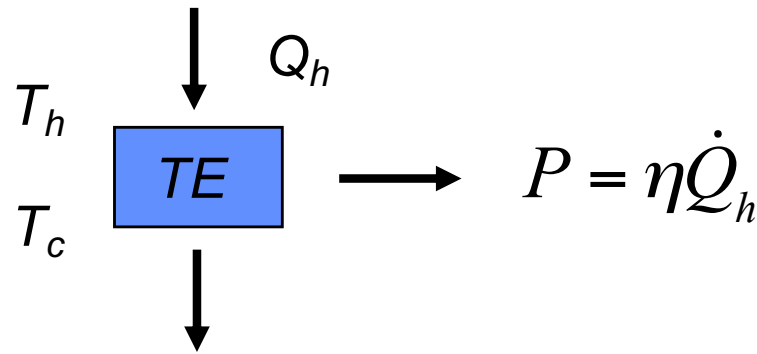
ZT for maximum Power

not 'power factor': Proof by Contradiction

1) Suppose material or device design based on power not ZT (lower efficiency η_P)

$$P = \alpha^2 \sigma \frac{A}{l} \Delta T^2 \frac{R_L / R_{TE}}{(1 + R_L / R_{TE})} \quad \theta_{TE} = \theta_{Hx} = \frac{l}{\kappa_{TE} A f}$$

2) Take same System Design: same heat flux $\dot{Q}_h$ at same ΔT ,
Use TE designed for efficiency (maximize ZT) η_{ZT}



3) Because $P = \eta \dot{Q}_h$, ZT device produces more power



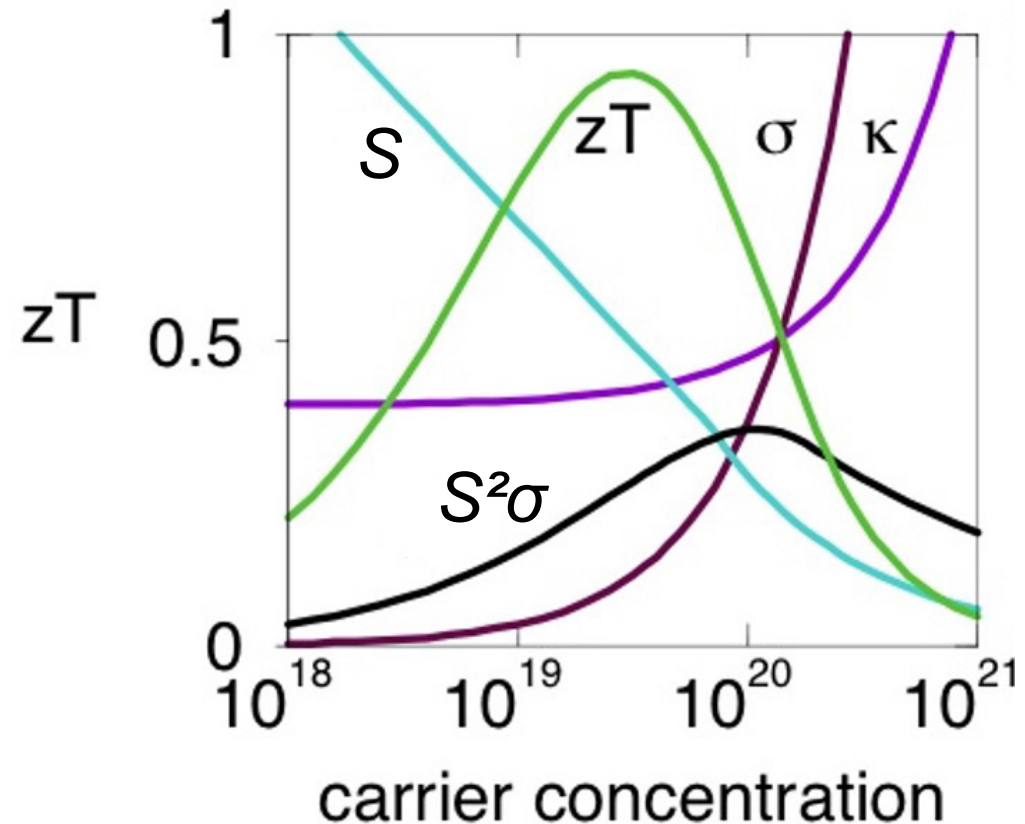
“Promising TE Material” ?

Maximum zT depends on Quality Factor, B

$$B \sim \frac{\mu_w}{\kappa_L}$$

Weighted Mobility μ_w

Lattice Thermal Conductivity κ_L

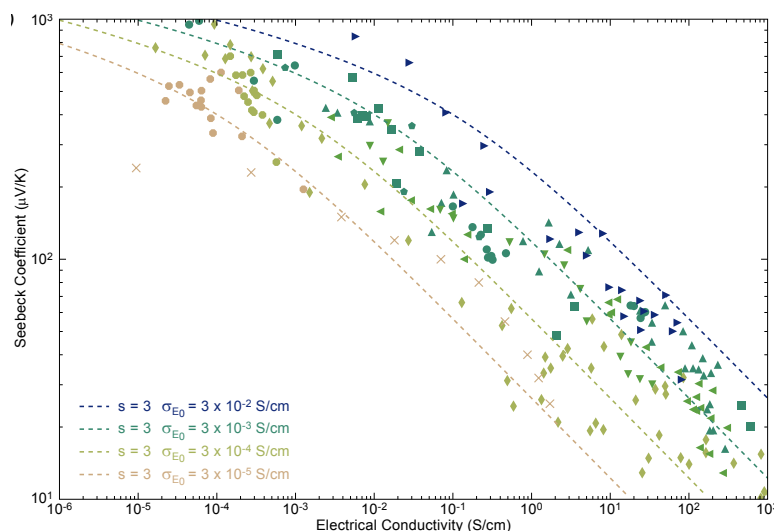
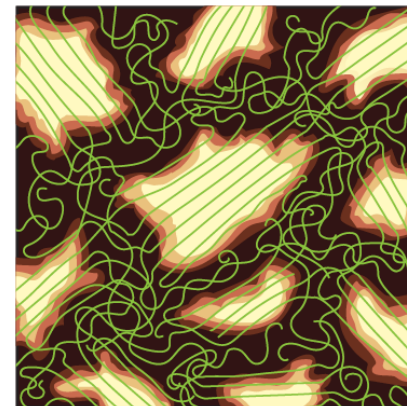


“Better Electronic Properties” = higher μ_w (not S , $S^2\sigma$)

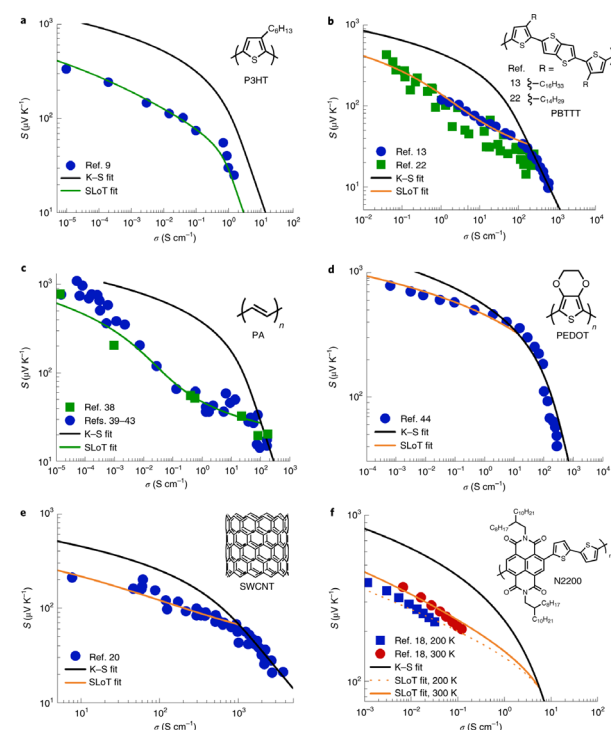
“Better Thermal Properties” = lower κ_L

μ_W for Disordered Materials

- Model how properties change with doping
- Helps identify transport mechanism
- Quantify Localization
- Predicts peak zT



polyacetylene (◆); PBTTT (■◀); P2TDC17-FT4 (◆)
P3HT (●▲); PDPP3T (▶); PSBTBT (▼); P3HTT (●)



S. Kang and Snyder, *Nature Materials* **16**, 252 (2017)

S. Gregory et al, *Nature Materials* **20**, 1414 (2021)

M Agne et al, *Matter* **4**, 2970 (2021)



Ball-Milling Synthesis

Complex alloys typically melt incongruently
melt produces inhomogeneous materials

Solution = Milling + Annealing of solid
Solid-state reaction diffusion limited

reaction time t

particle size l

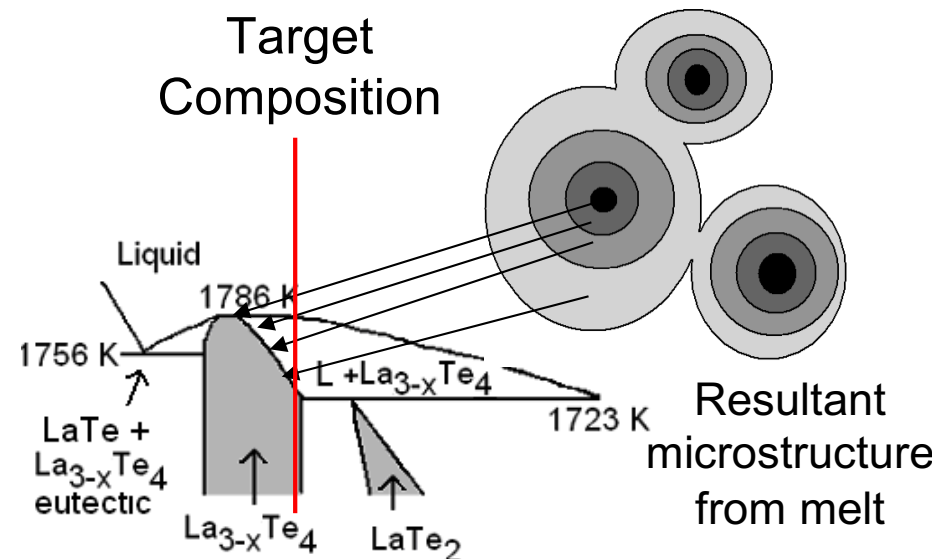
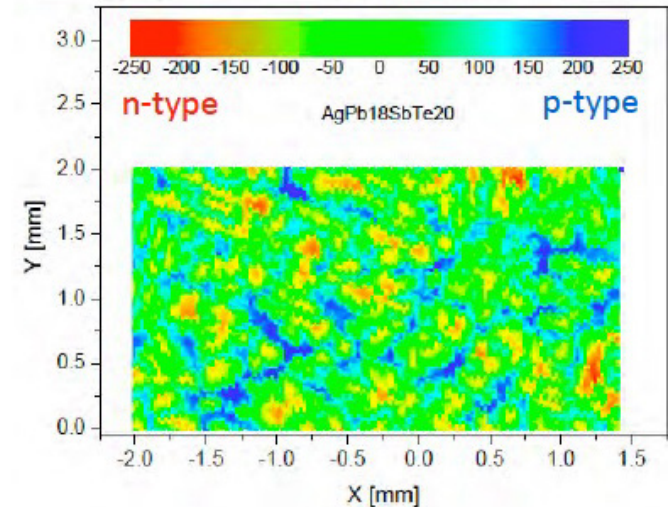
diffusion coefficient D

$$t \approx \frac{l^2}{D}$$

Mechanical Alloying - Ball Milling

Reduce particle size l to 10-100nm

speed reaction time at low temperature



Rapid Hot Press vs SPS

Spark? Plasma?

Want to drive ions with DC current?

Radio Frequency (RF) Heating

System	HP	SPS	RHP
Cost	Med	High	Low
System size	Med	Large	Small
Heating rate	Slow	Fast	Fast
Chemistry effect	None	Problem	None
Design flexibility	Med	Small	Large
Scale up	Easy	Hard	Easy

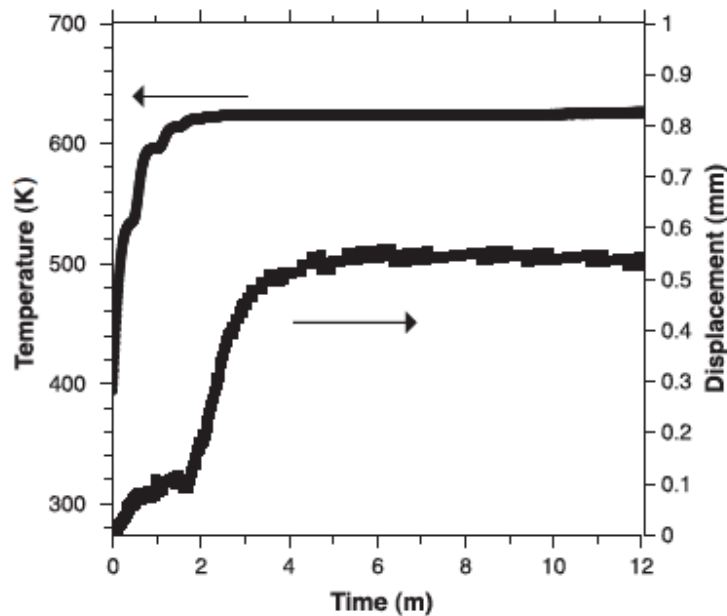


FIG. 2. Temperature vs ram displacement for consolidation of sample at 623 K for 10 min.

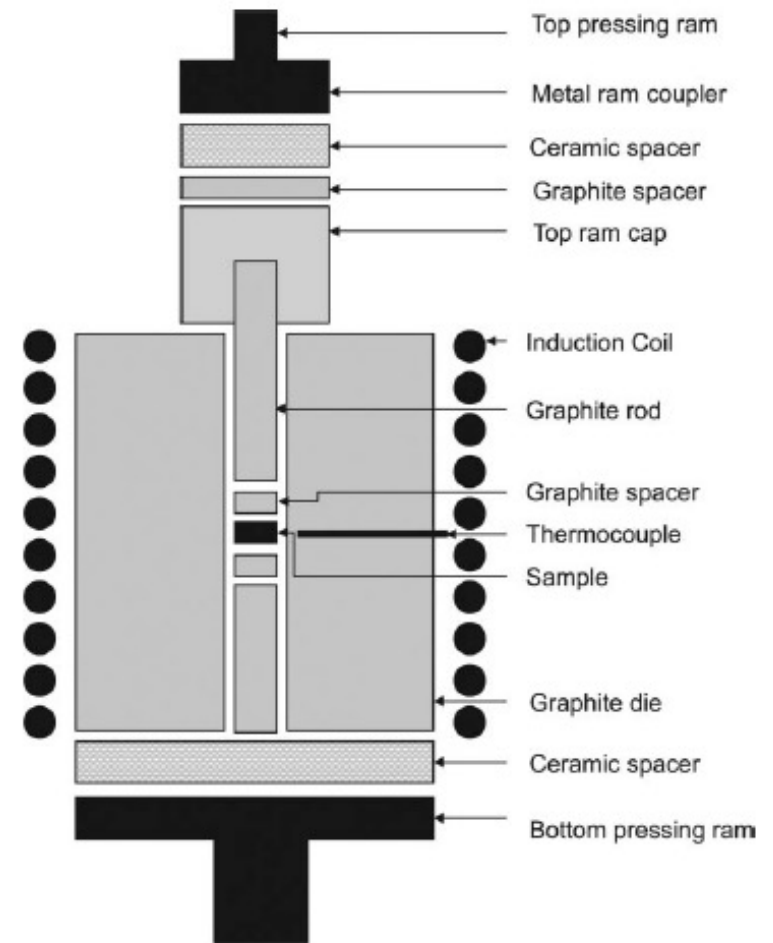
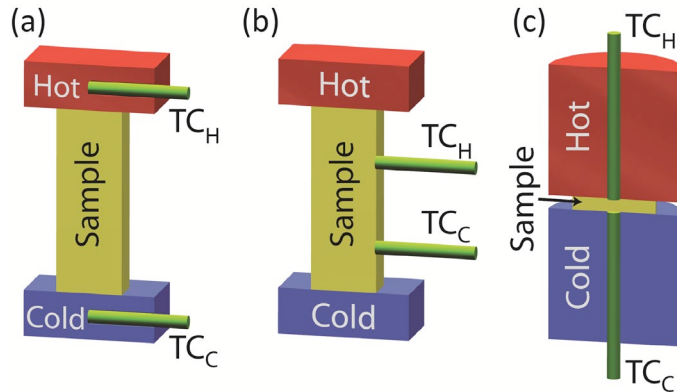
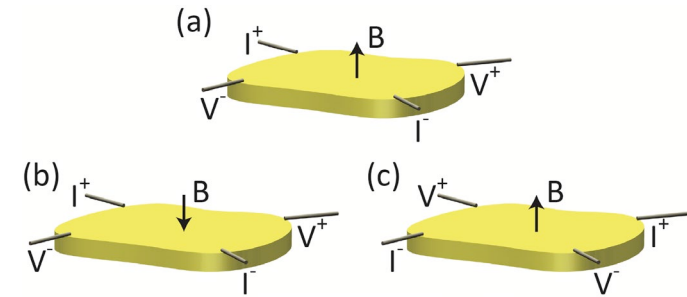


FIG. 1. Schematic of induction hot press setup.

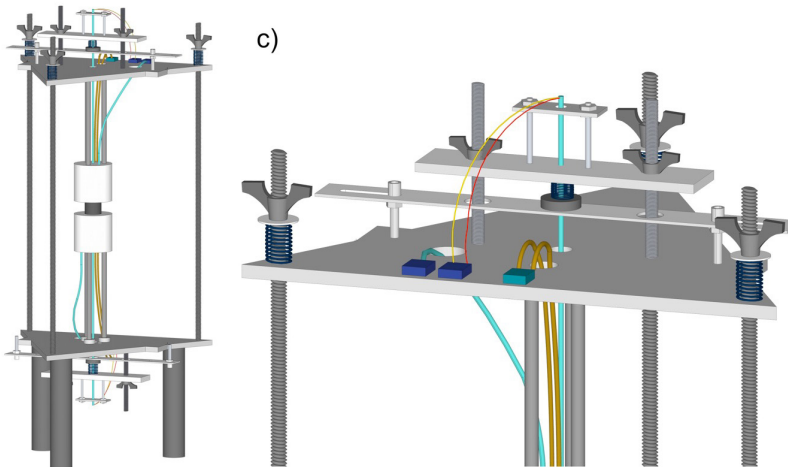
Measurement Techniques



Seebeck to avoid
Cold Finger Effect



Van der Pauw for Electrical
Conductivity and Hall Effect

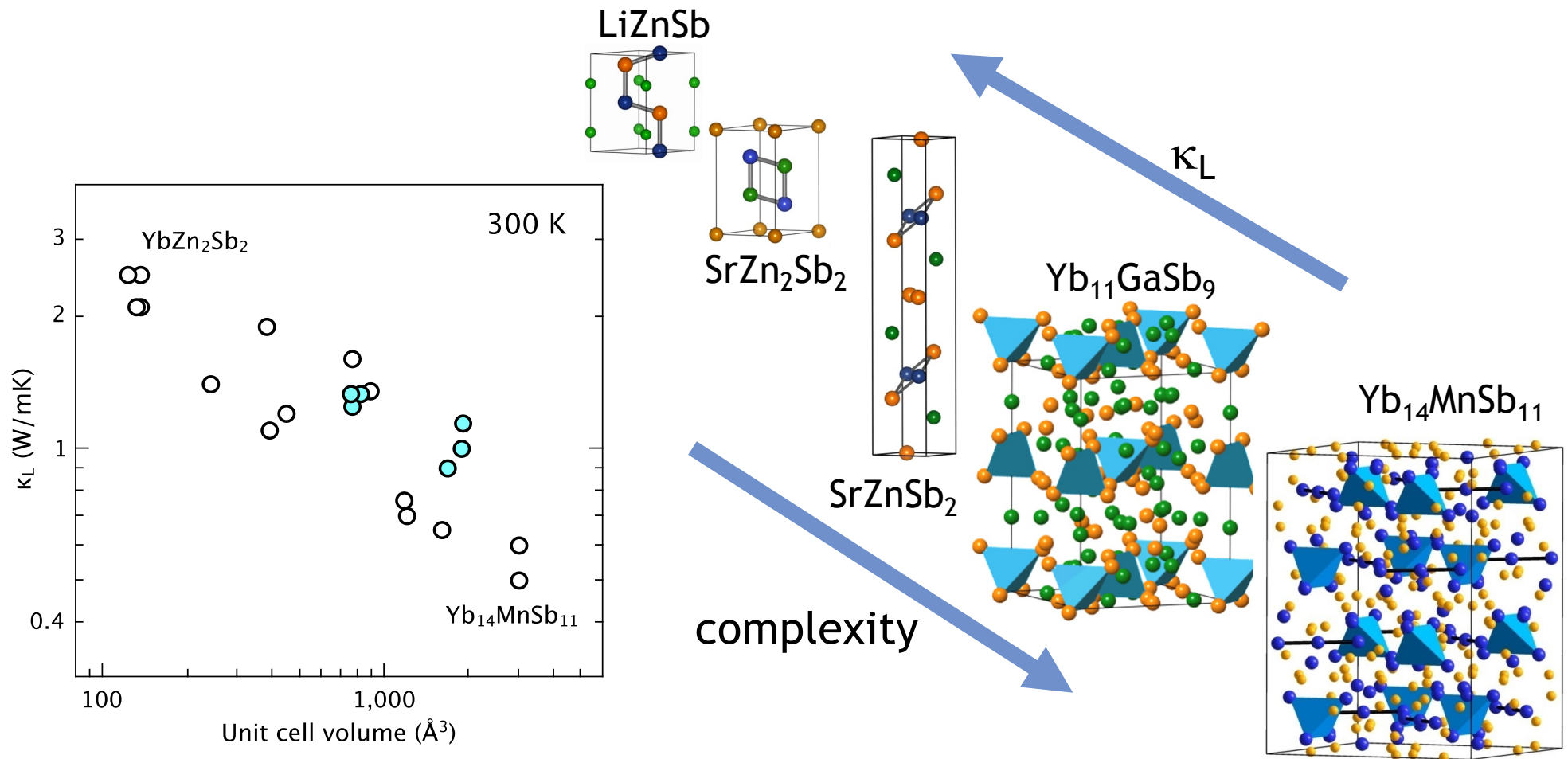


Caltech 2006-2014



Thermoelectrics
Caltech Materials Science

Zintl Thermoelectrics

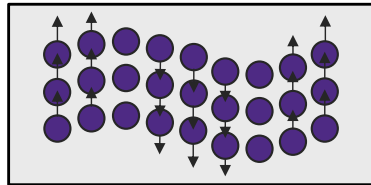


Thermal Conductivity model

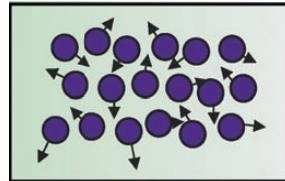
$$\kappa_L = \kappa_U + \kappa_{optic}$$

$$= \frac{A}{T} + B$$

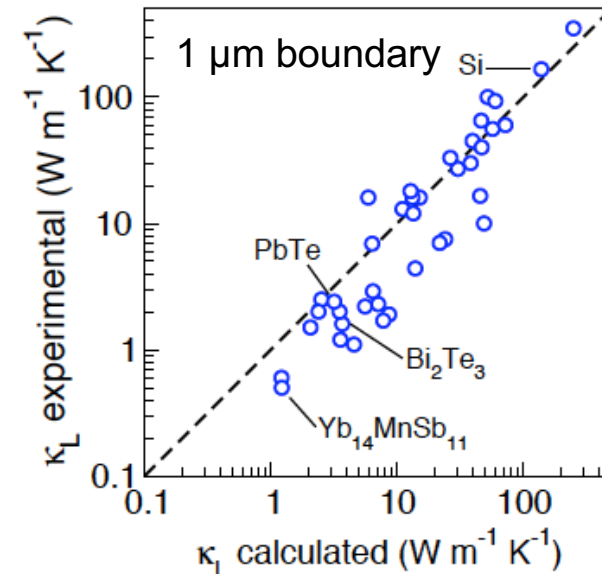
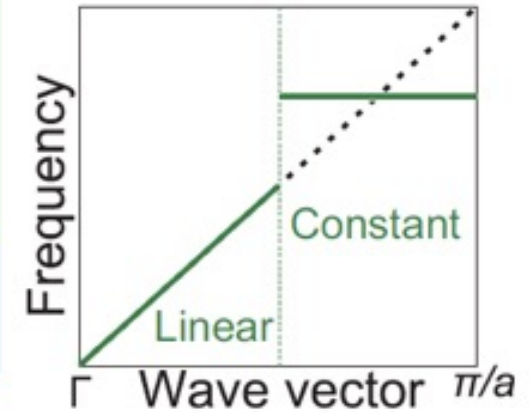
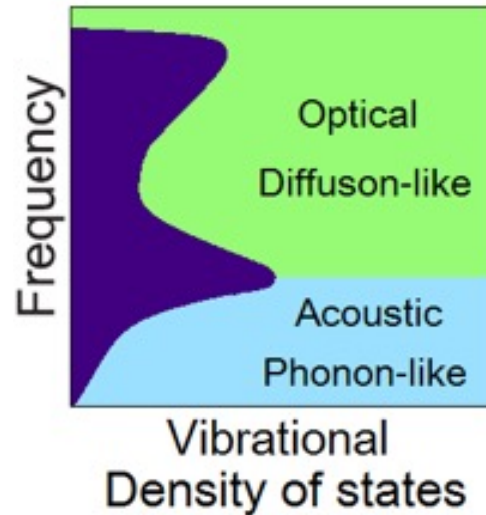
Acoustic phonons
Umklapp Scattering



Diffusons at κ_{min}



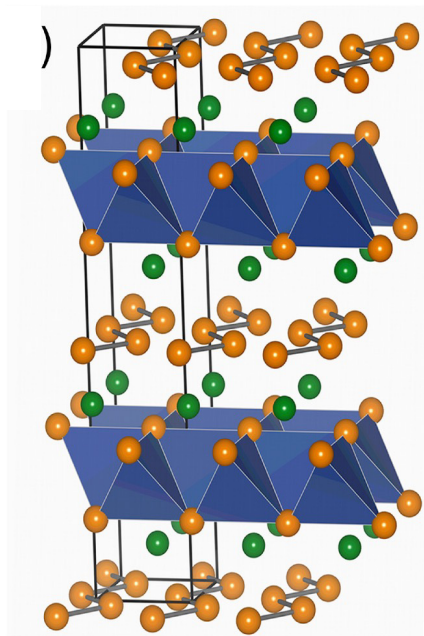
$$\kappa_{optic} \sim 0.76 \frac{k_B v_s}{V^{\frac{2}{3}}} \left(1 - N^{\frac{-2}{3}}\right)$$



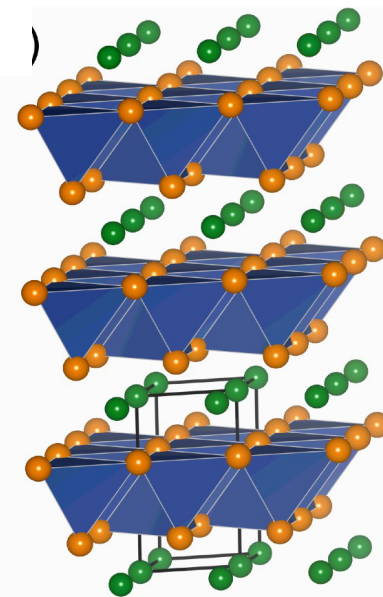
SrZnSb_2 , SrZn_2Sb_2 and Mg_3Sb_2



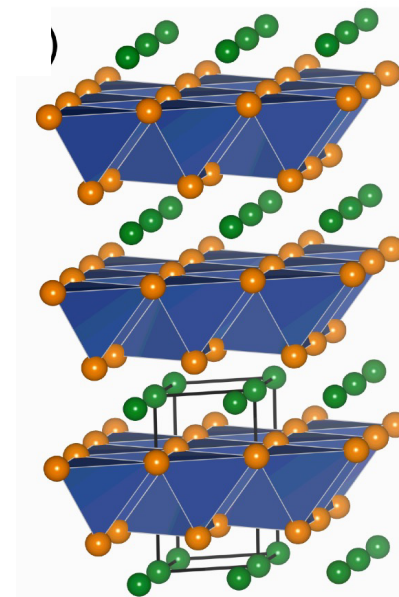
SrZnSb_2



SrZn_2Sb_2



Mg_3Sb_2



Toberer et. al. *Dalton Trans.*, **39**, p. 1046, (2010)
Gascoin et. al. *Adv. Funct. Mat.*, **15**, p. 1860, (2005)
Condon et al, *J. Solid State Chemistry* **179** 2252 (2006)

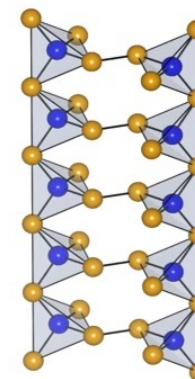
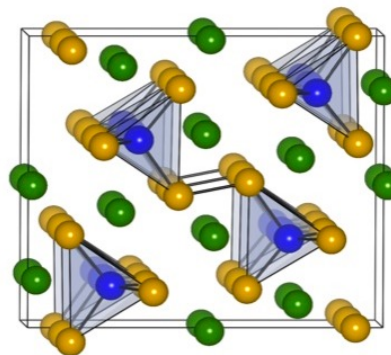


Some Zintl Chain Structures



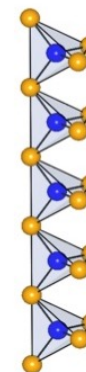
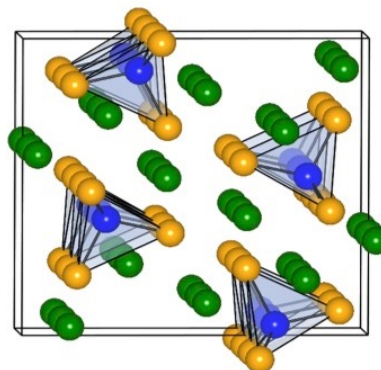
chains linked by Sb-Sb bonds to form "ladders"

26 atoms per cell



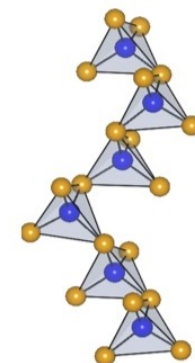
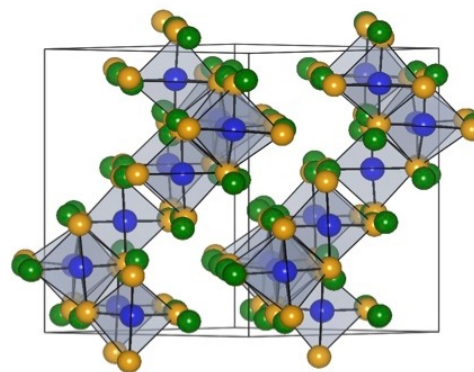
simple corner sharing linear chains

28 atoms per cell

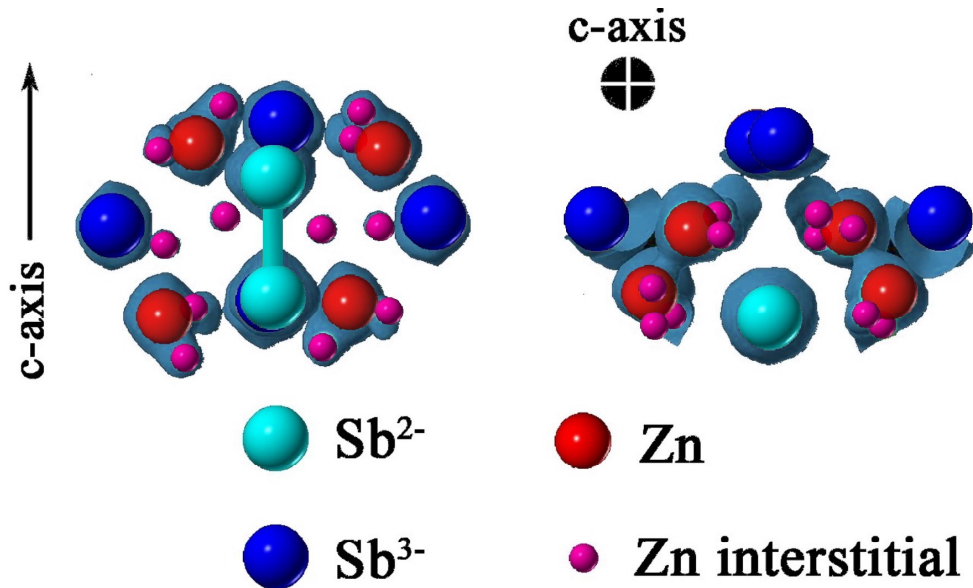
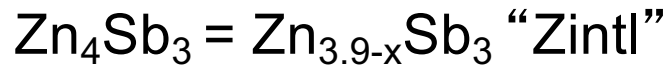


non-linear corner sharing chains with 4-tetrahedra periodicity

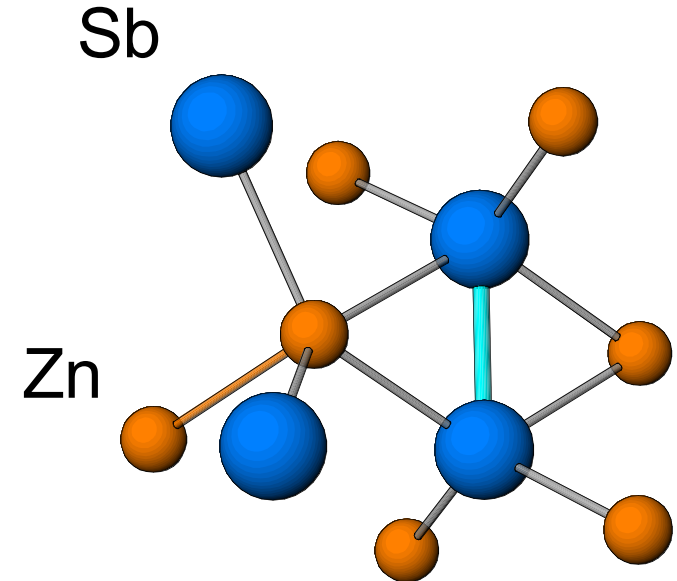
56 atoms per cell



Zn₄Sb₃ and ZnSb



Extra Zn found in interstitial sites



ZnSb: $\text{Sb}^{2-}\text{-Sb}^{2-}$ dimers

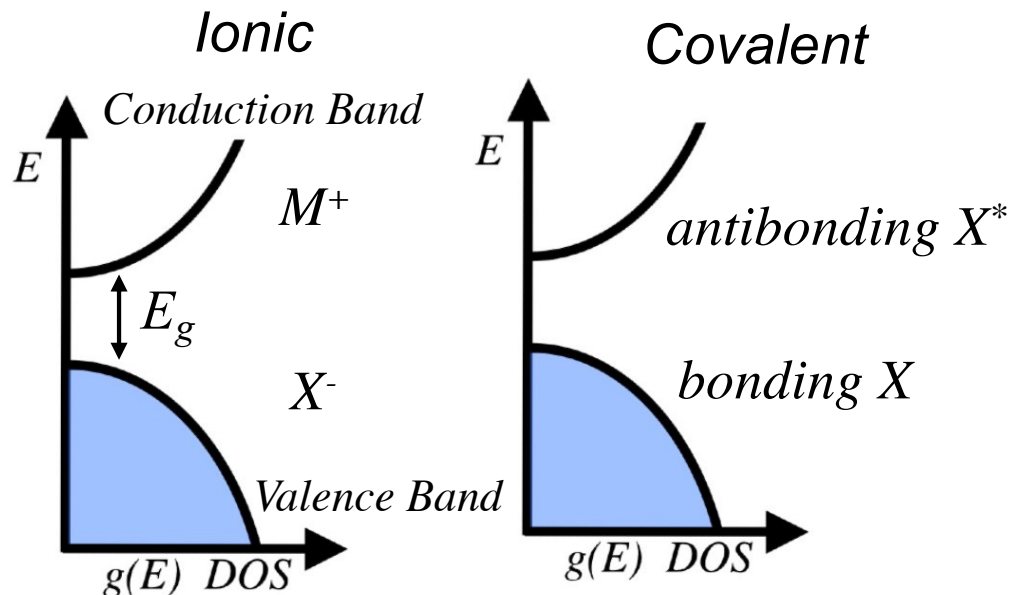
Zintl Valence Semiconductors

$$V_c = e_c - b_c \quad V_a = e_a + b_a - 8$$

e valence electrons in atom

each bond b reduces |valence| by 1

Zintl Phase
Valence Balance
= Semiconductor



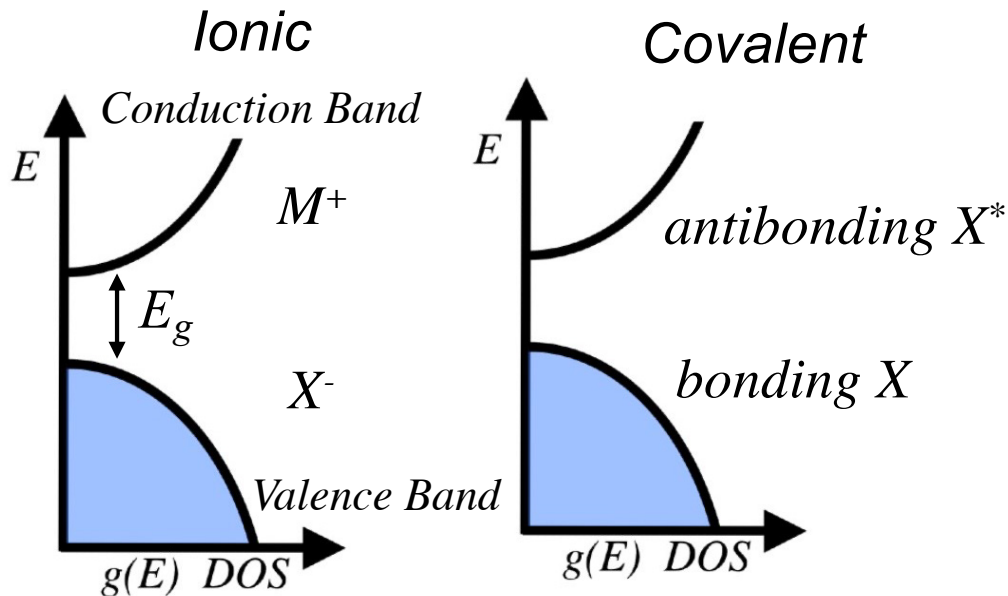
Zintl Valence Semiconductors

$$V_c = e_c - b_c \quad V_a = e_a + b_a - 8$$

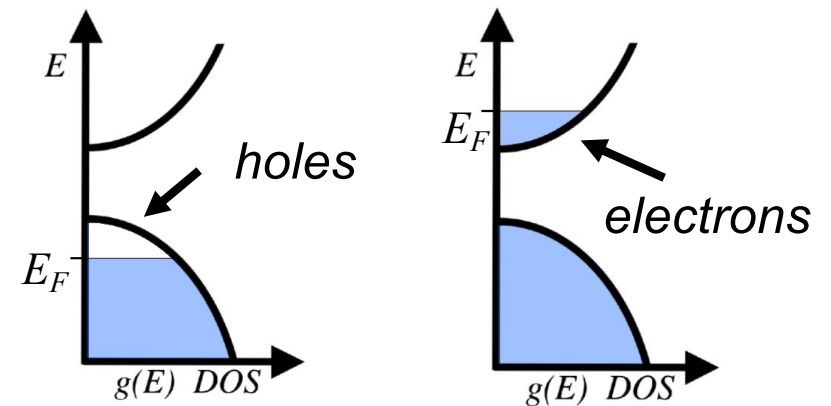
e valence electrons in atom

each bond b reduces |valence| by 1

Zintl Phase
Valence Balance
= Semiconductor

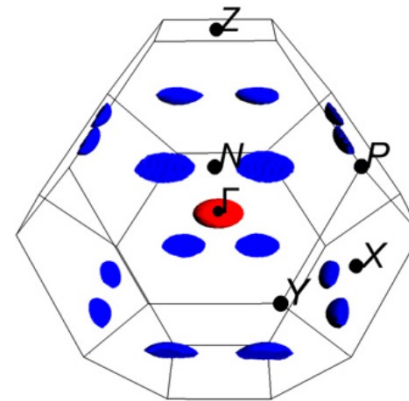
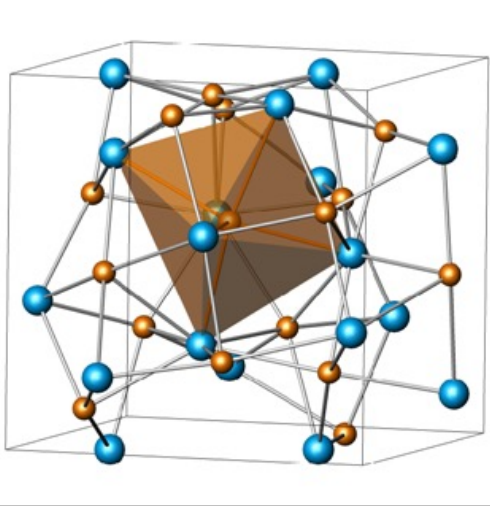


Zintl Metals
Valence ImBalance
= doped semiconductor

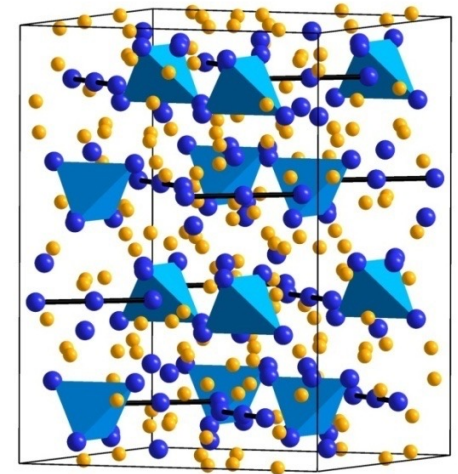


La₃Te₄ - Yb₁₄MnSb₁₁

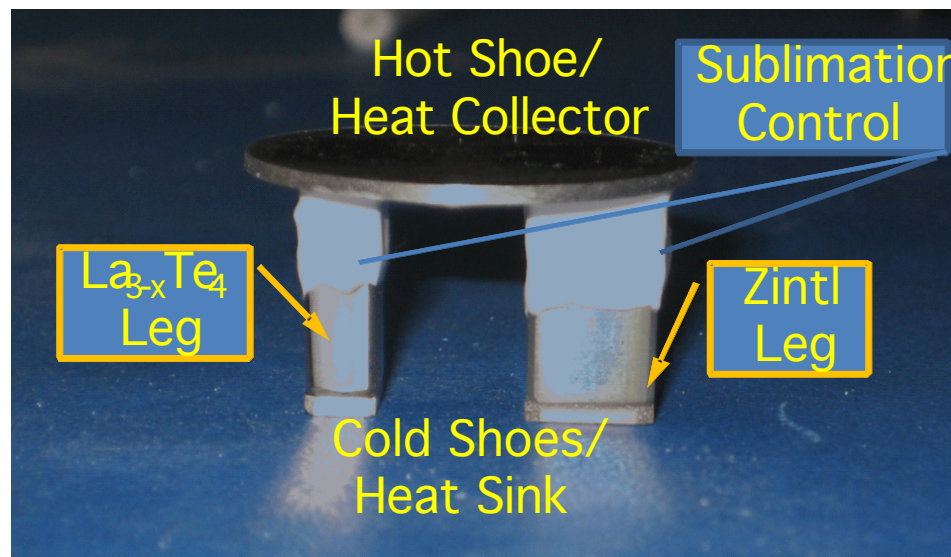
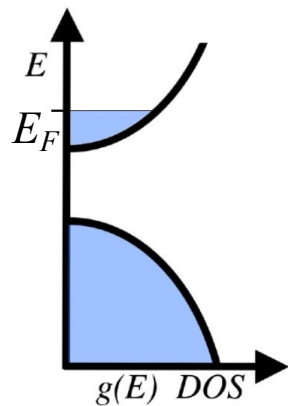
Zintl Metals developed for NASA



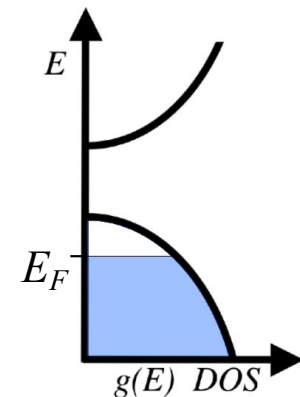
Fermi Surface



La₃Te₄
Exactly 1e⁻ extra



Yb₁₄MnSb₁₁
Exactly 1e⁻ less



Jean-Pierre Fleurial (JPL)

Perez, Wood Snyder *Science Advances*, 7, 9439 (2021)

May, Snyder *Phys Rev B*. 79 (15), 153101 (2009)



Thermoelectrics

Northwestern Materials Science and Engineering

Other Thermoelectric Zintl Metals



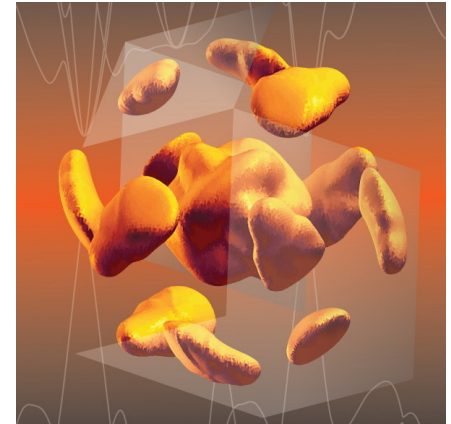
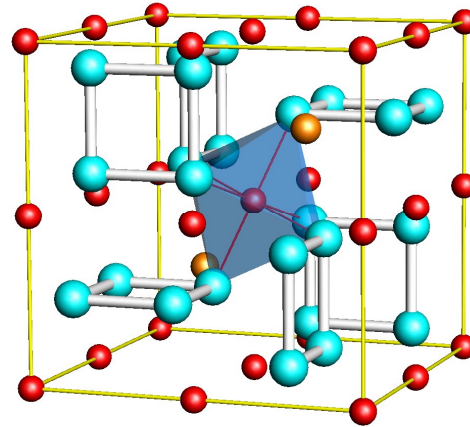
Filled Skutterudites

Sb square rings $2b\text{-Sb}^{-1}$

$\text{Co}^{+3}\text{Sb}_3$ valence semicond.

$\text{La}^{+3}\text{Fe}_4^{+2}\text{Sb}_{12}$ Zintl Metal

1 hole/fu



Fermi Surface (n-type)

Mo_3Sb_7

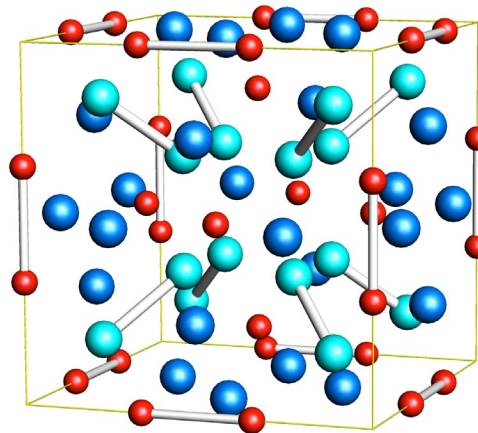
4x Sb dimers $1b\text{-Sb}^{-2}$

3x Sb isolated $0b\text{-Sb}^{-3}$

Mo-Mo dimer $1b\text{-Mo}^{+5}$

2 holes/FU = metal

- $\text{Mo}_3\text{Sb}_5\text{Te}_2$ for SC



Y. Tang, Gibbs, Snyder, *et al* *Nature Materials* **14**, 1223 (2015)

Gascoin, *et al* *J. Alloys. Compounds* **427**, 324 (2007)

Kauzlarich, Snyder *et al*, *Dalton Trans.* p. 2099 (2007)

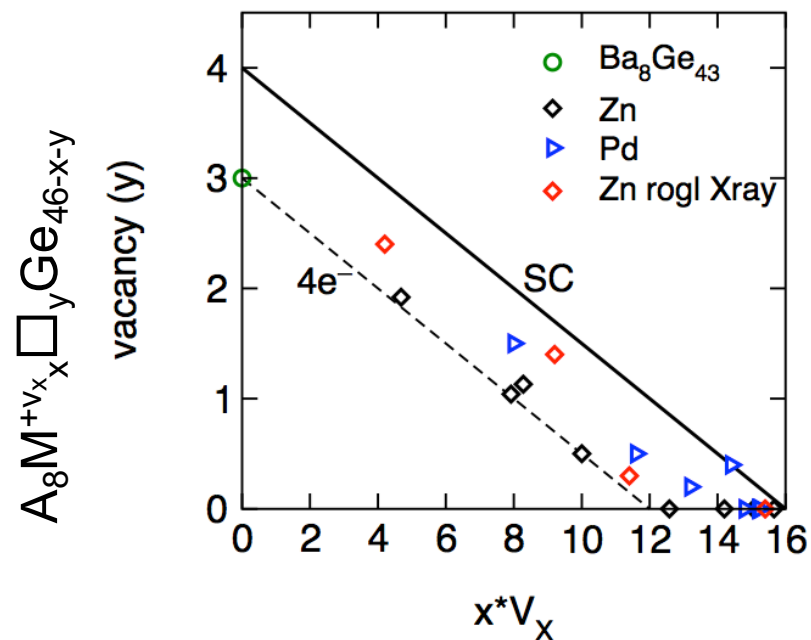
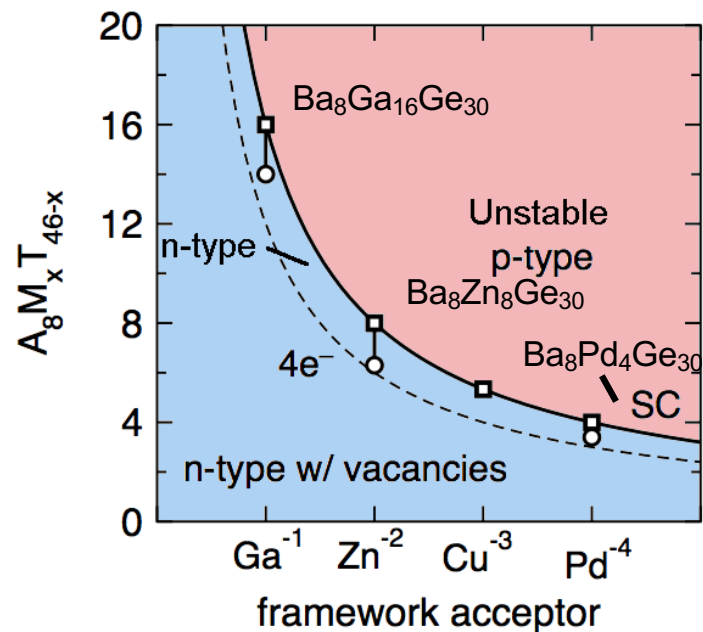
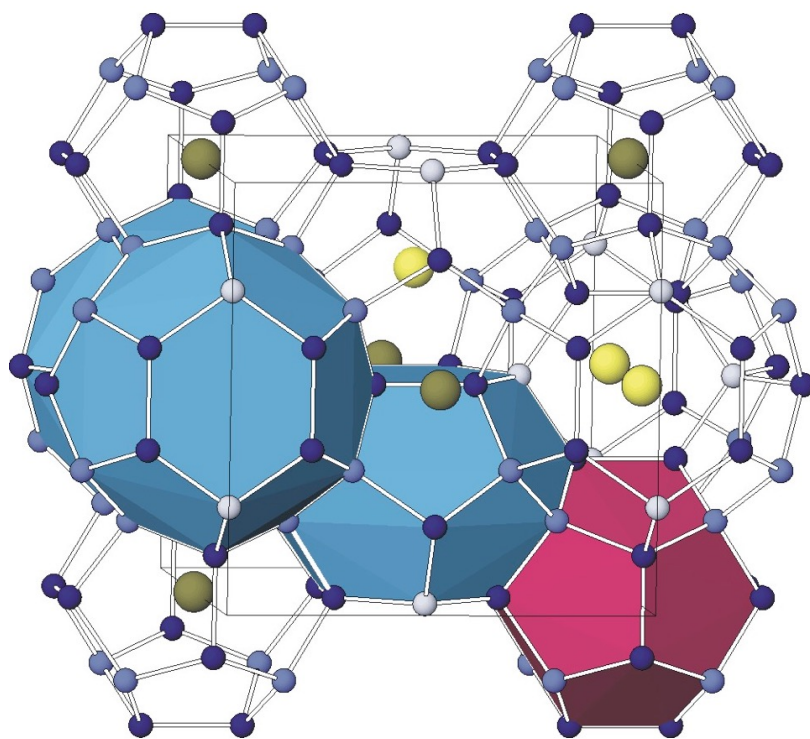


Thermoelectrics

Northwestern Materials Science and Engineering

Clathrates

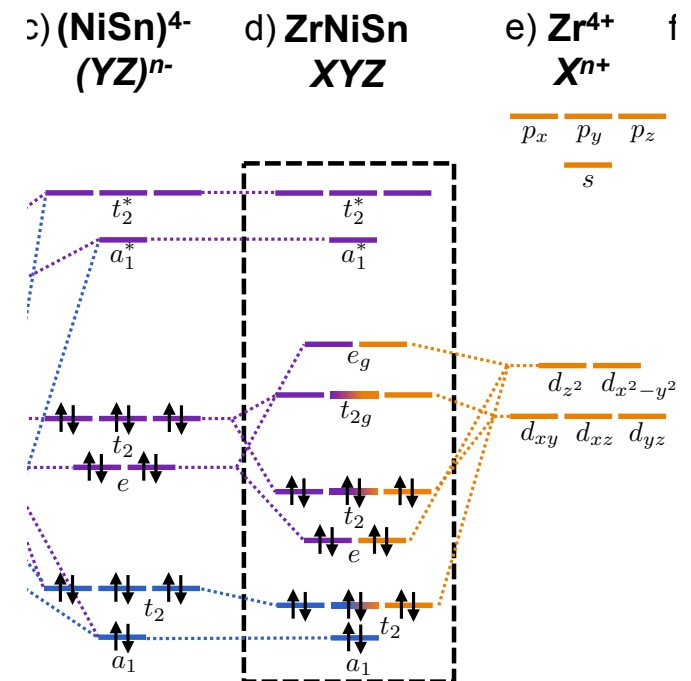
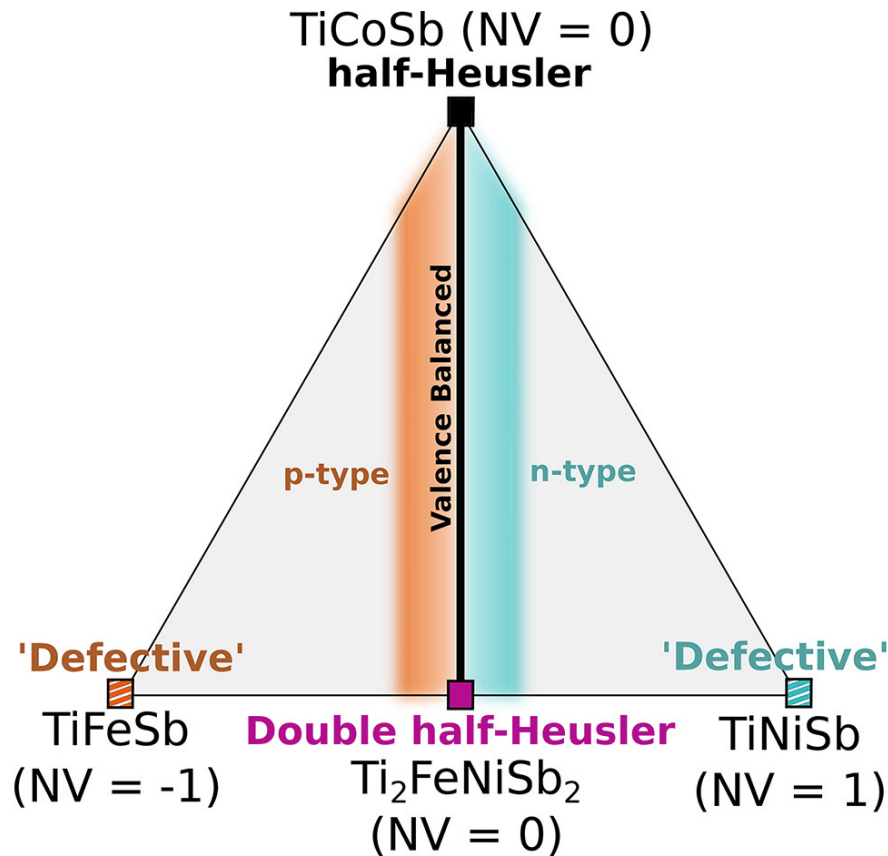
Most compositions near
Zintl-valence balance



Half-Heuslers as Zintl

Zintl-valence balance = Semiconductor

Valence imbalance = doped semiconductor



Cu/Ag Chalcogenides

Superionic thermoelectrics

glass-like thermal conductivity

good thermoelectric properties

Copper deposition

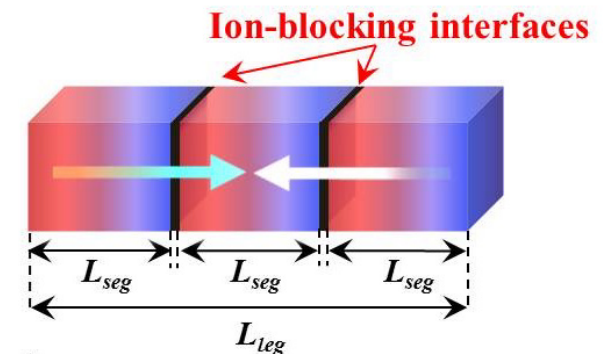
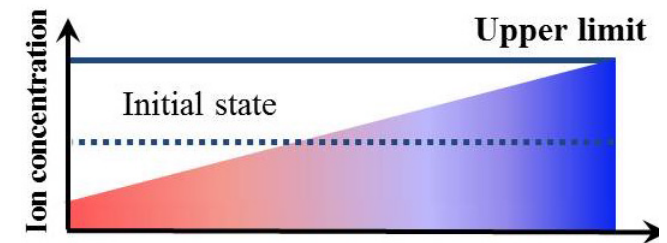
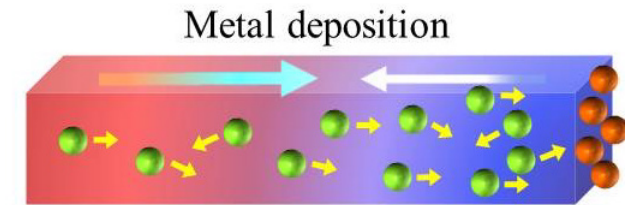
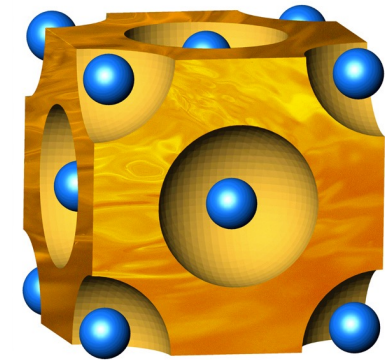
considered 'unstable'

Thermodynamic Stability

when below threshold potential

$$V_c = -\frac{1}{z_e F} \Delta \mu_{Cu}^{crit} - S^* \Delta T$$

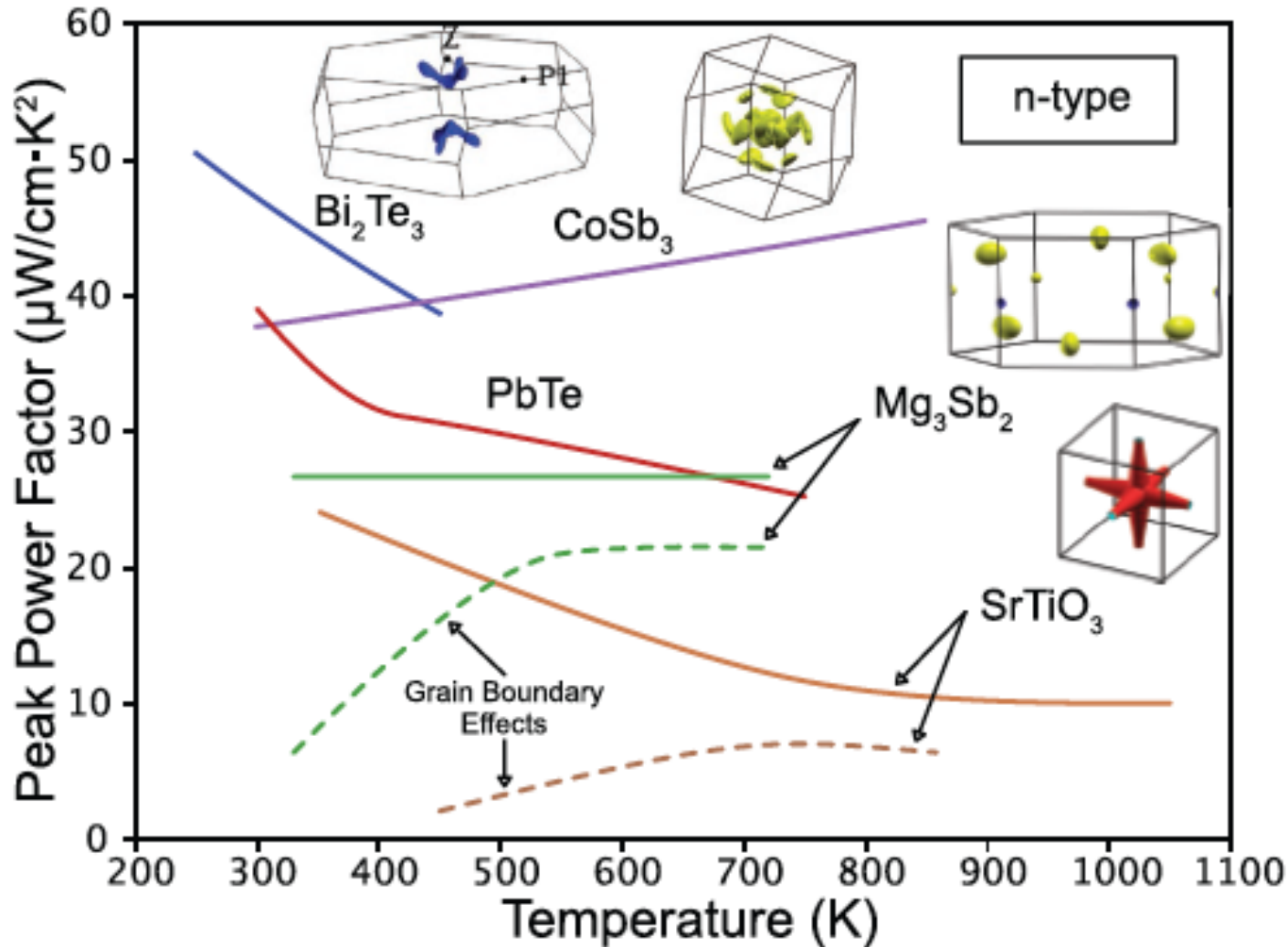
leads to strategy of ion blocking interfaces



Northwestern 2015-2024



TE with Complex Fermi Surfaces

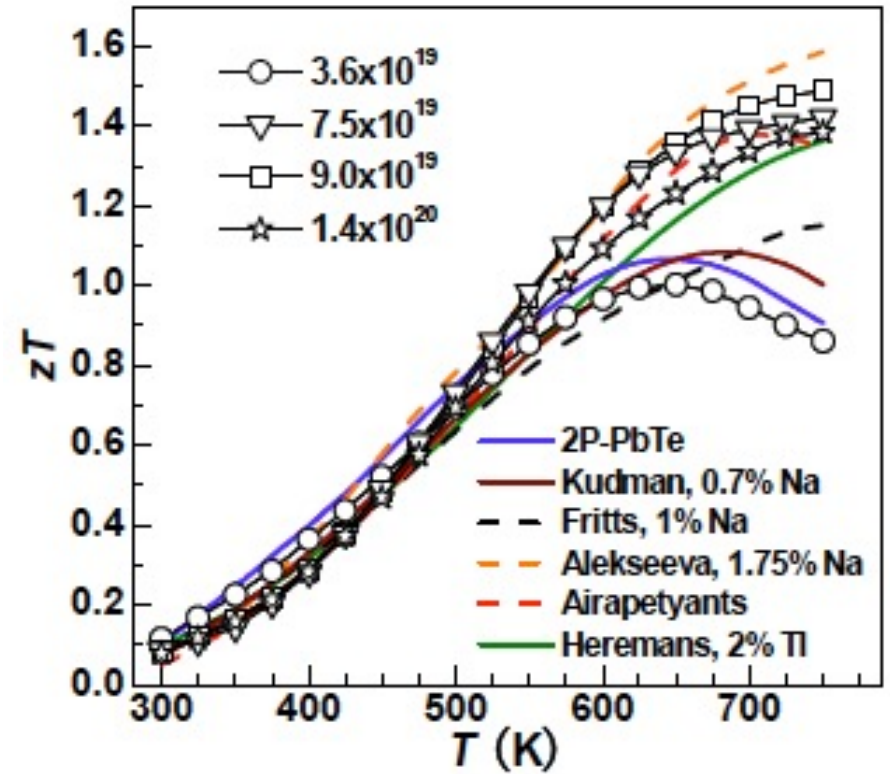
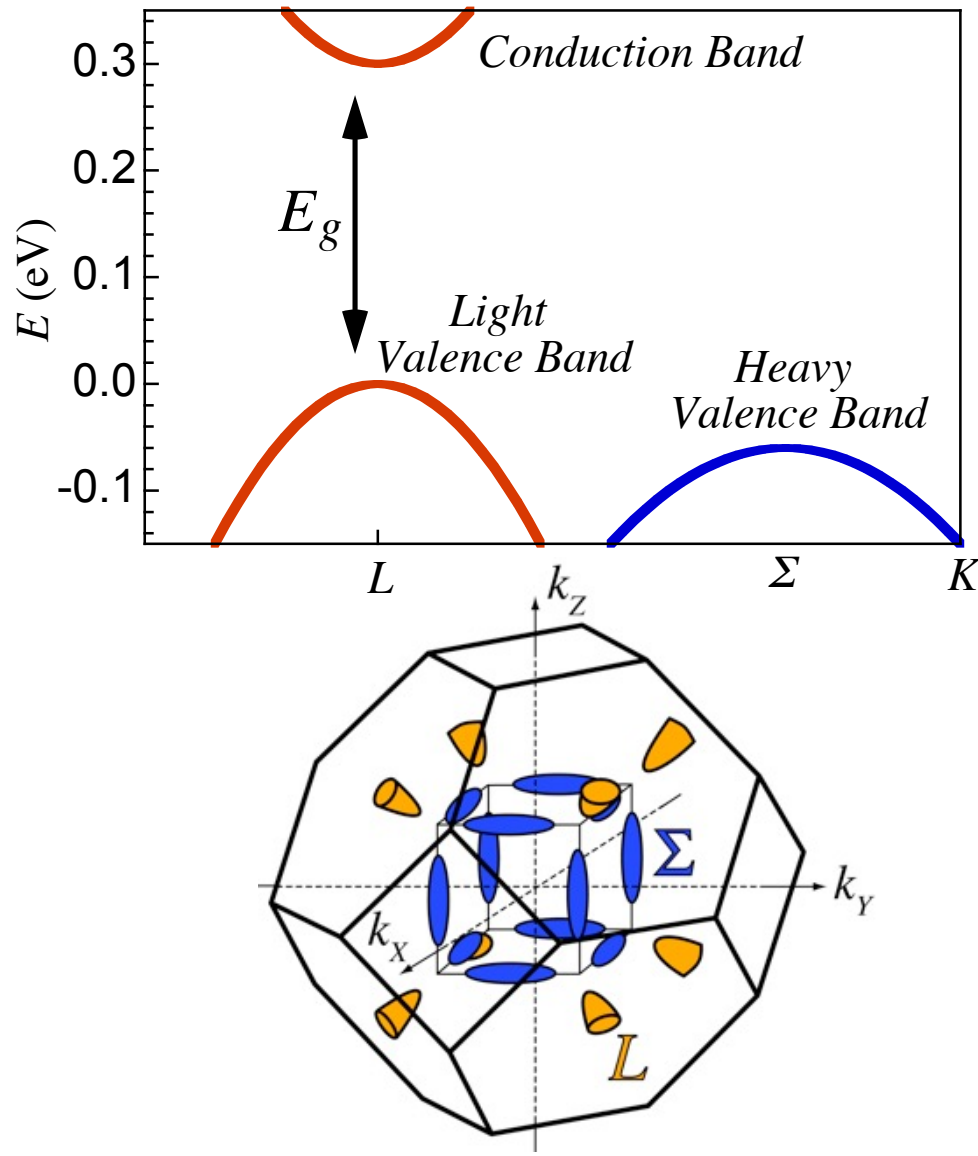


$$B \sim \frac{N_V}{m_I^* K_L}$$

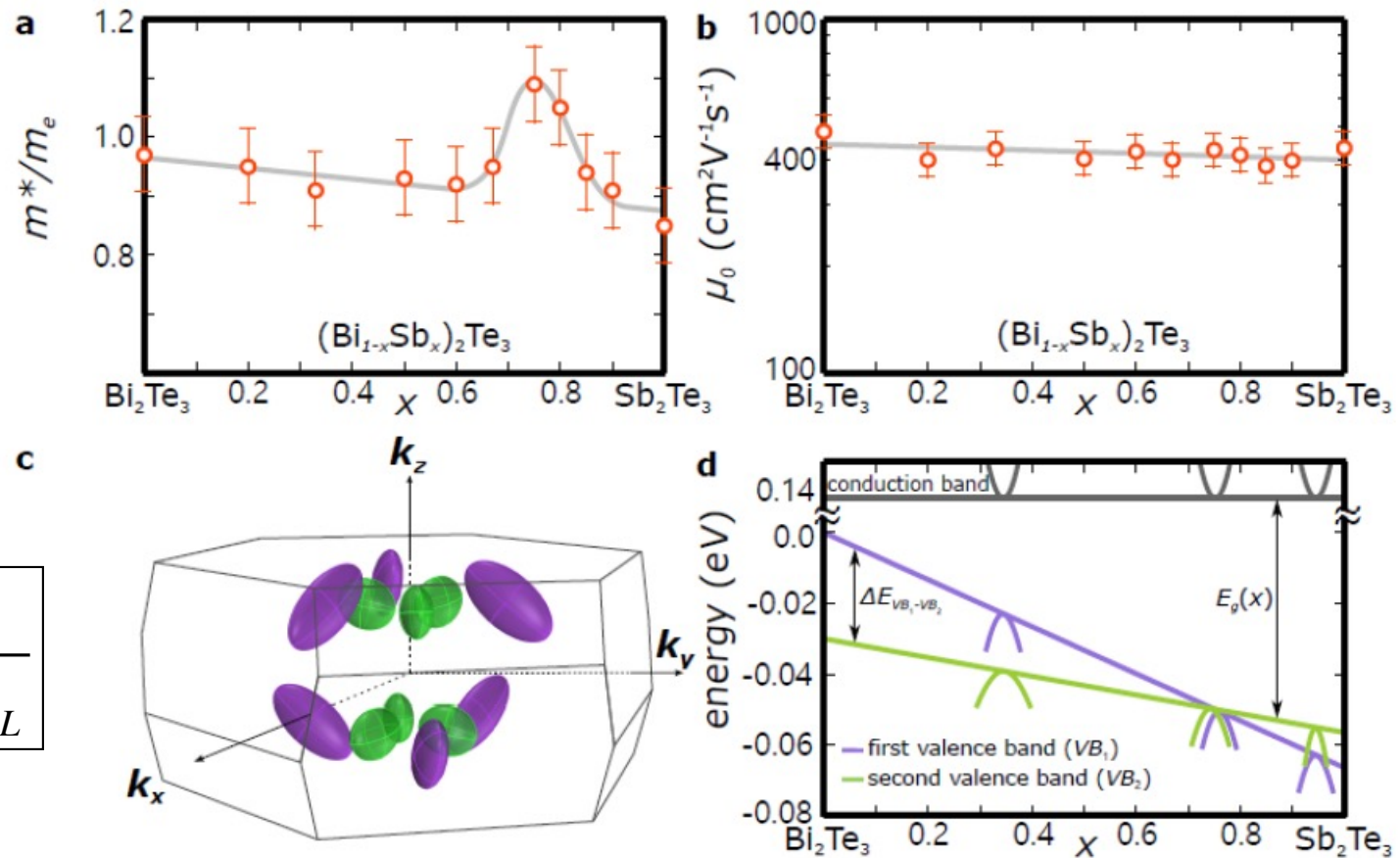
N_V = Fermi Surface complexity



Heavy and Light holes in PbTe

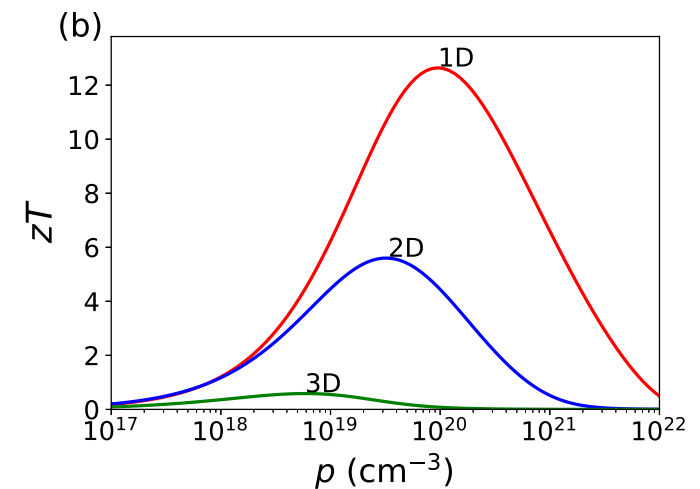
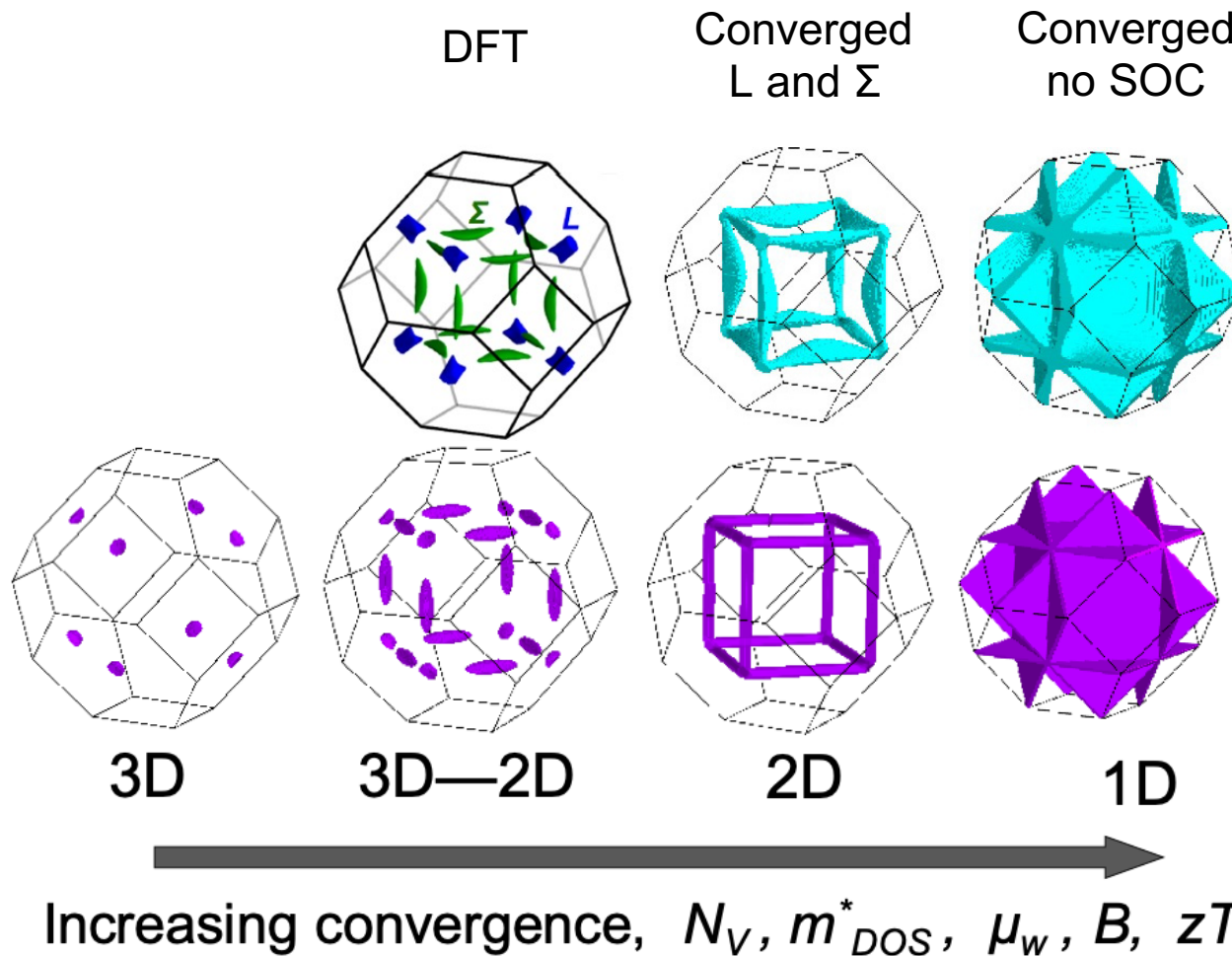


Band convergence in $(\text{Bi,Sb})_2\text{Te}_3$

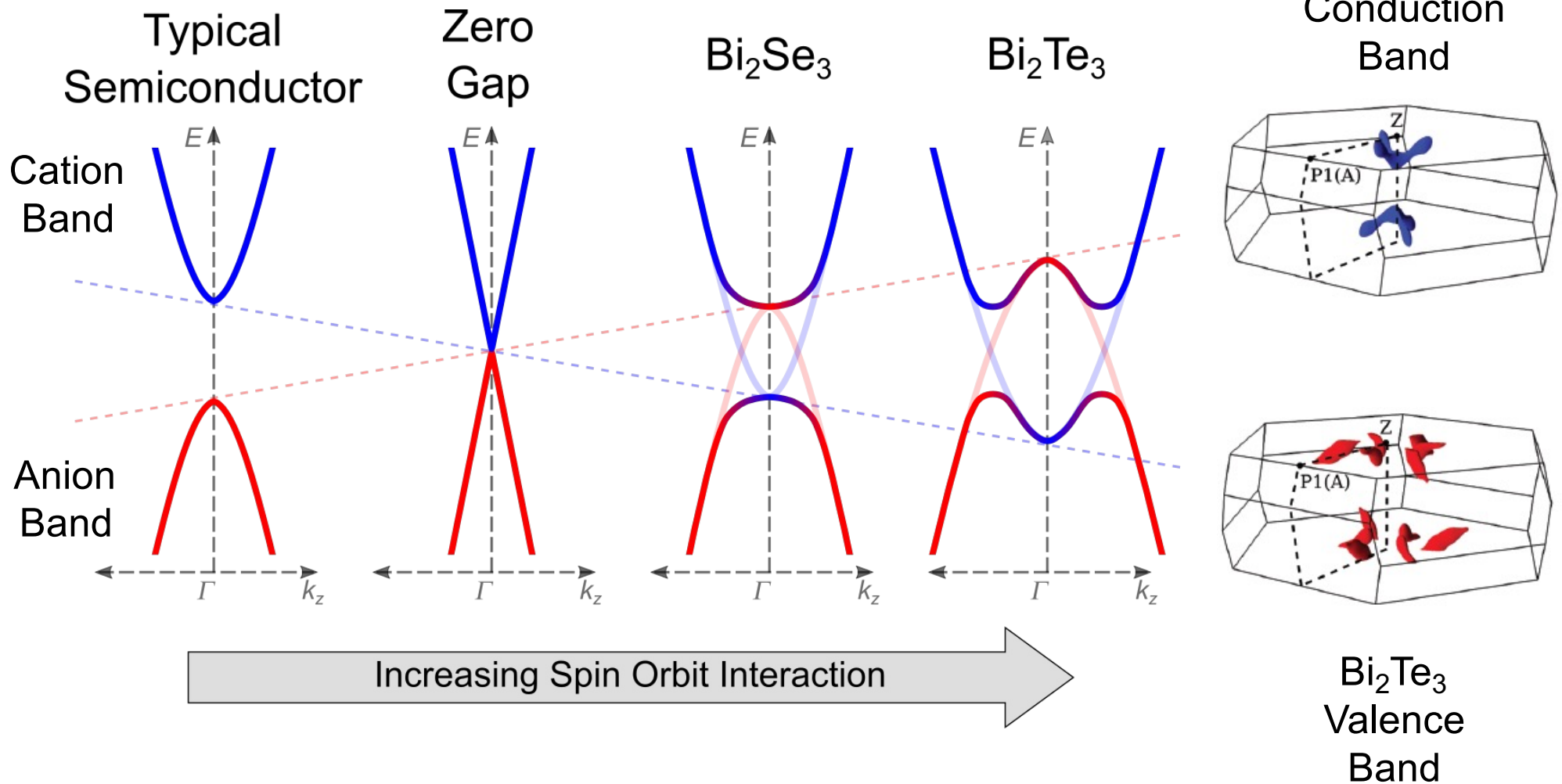


$$B \sim \frac{N_V}{m_I^* K_L}$$

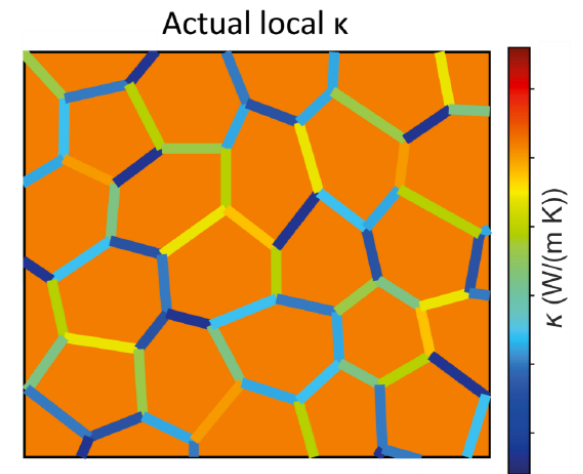
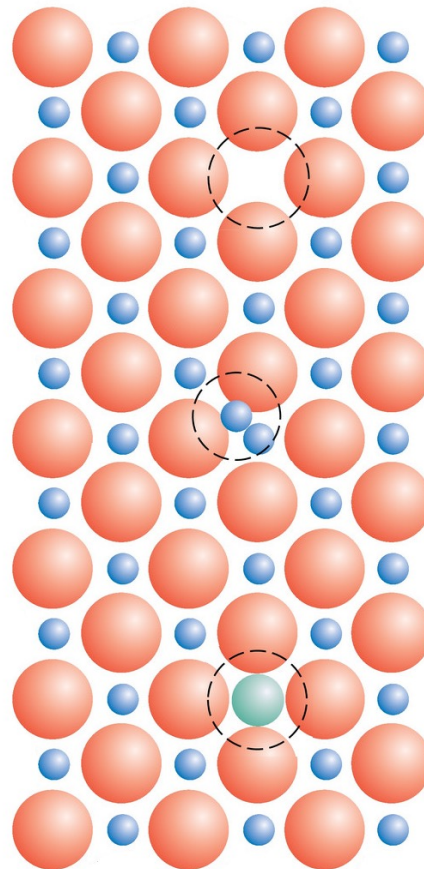
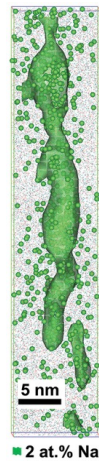
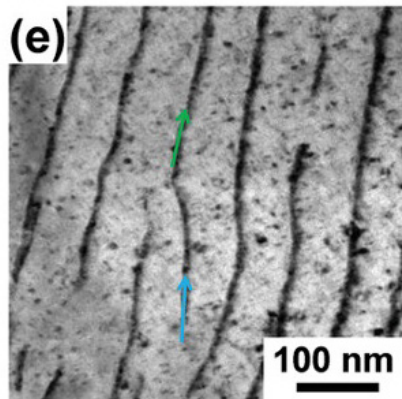
High zT predicted in low-D PbX



Why *some* TI are good TE



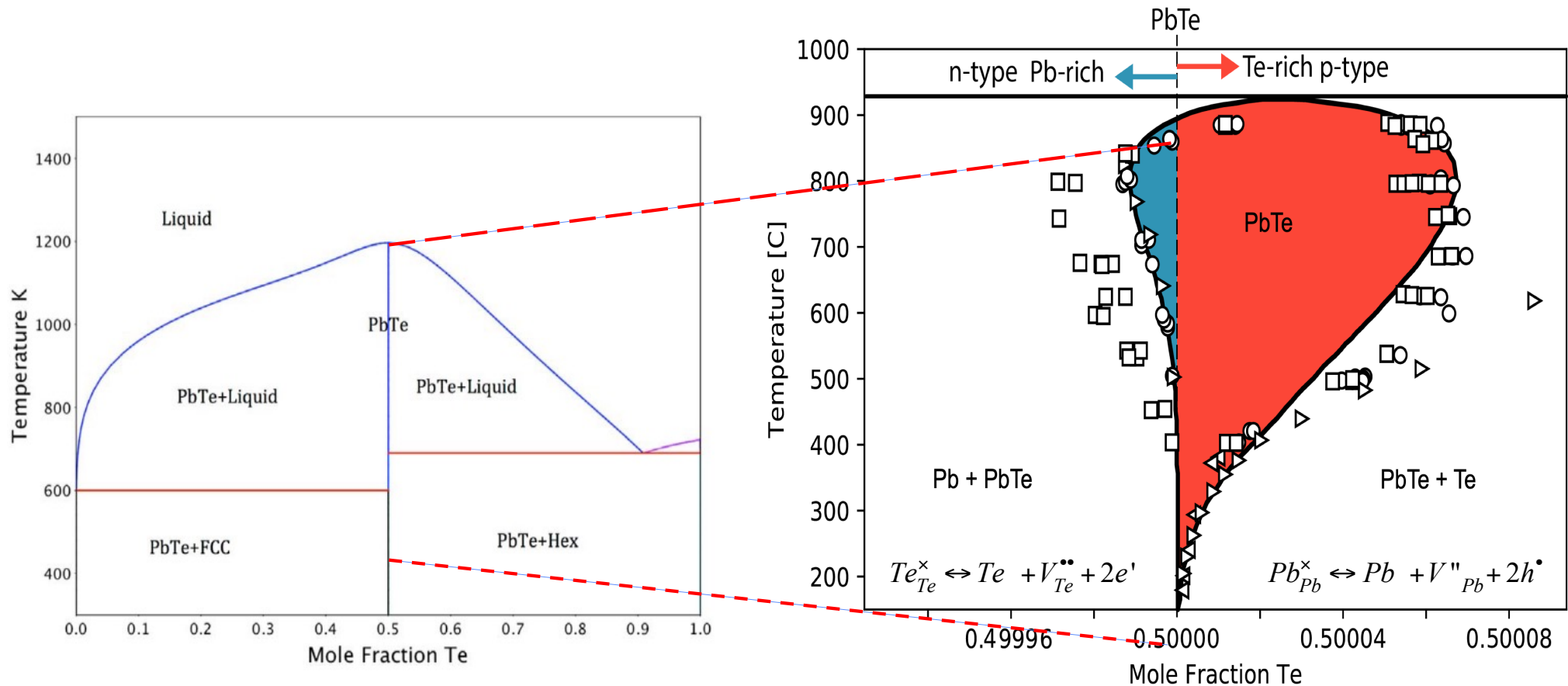
Defects



Two 'flavors' of PbTe

Pb-rich vs Te-rich defects change properties

Can now calculate phase diagram with DFT



J. Male et. al. *Materials Horizons* **6**, 1444 (2019)

Anand, Snyder, *Acc. Mater. Res.* **3**, 685 (2022)

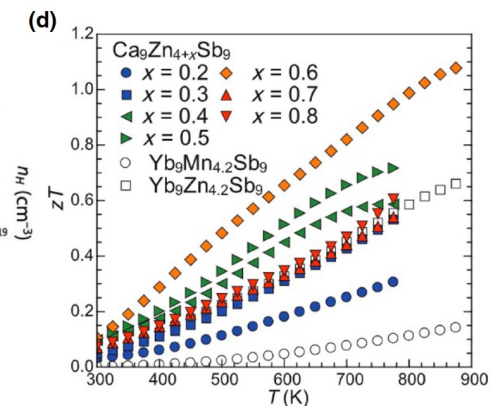
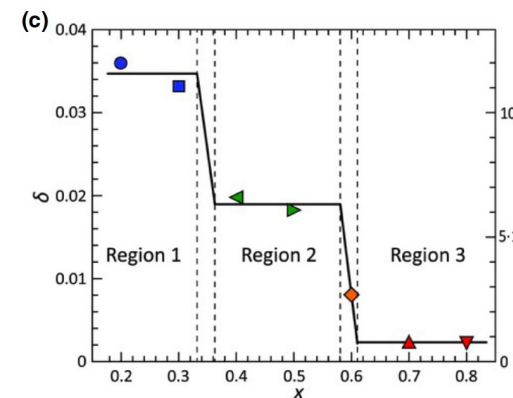
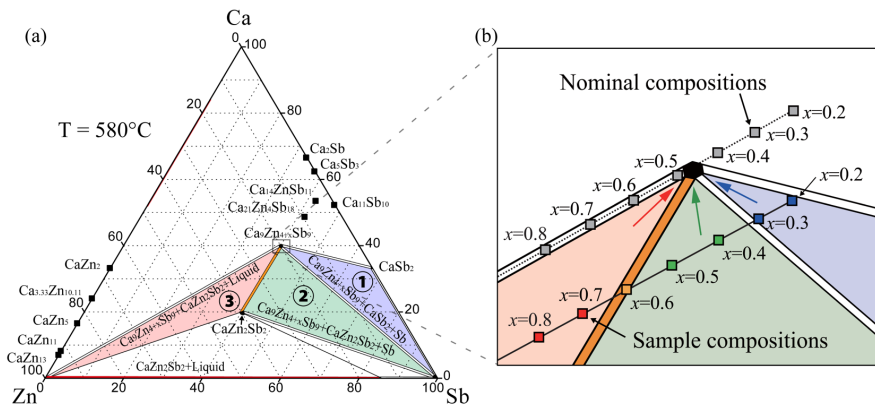
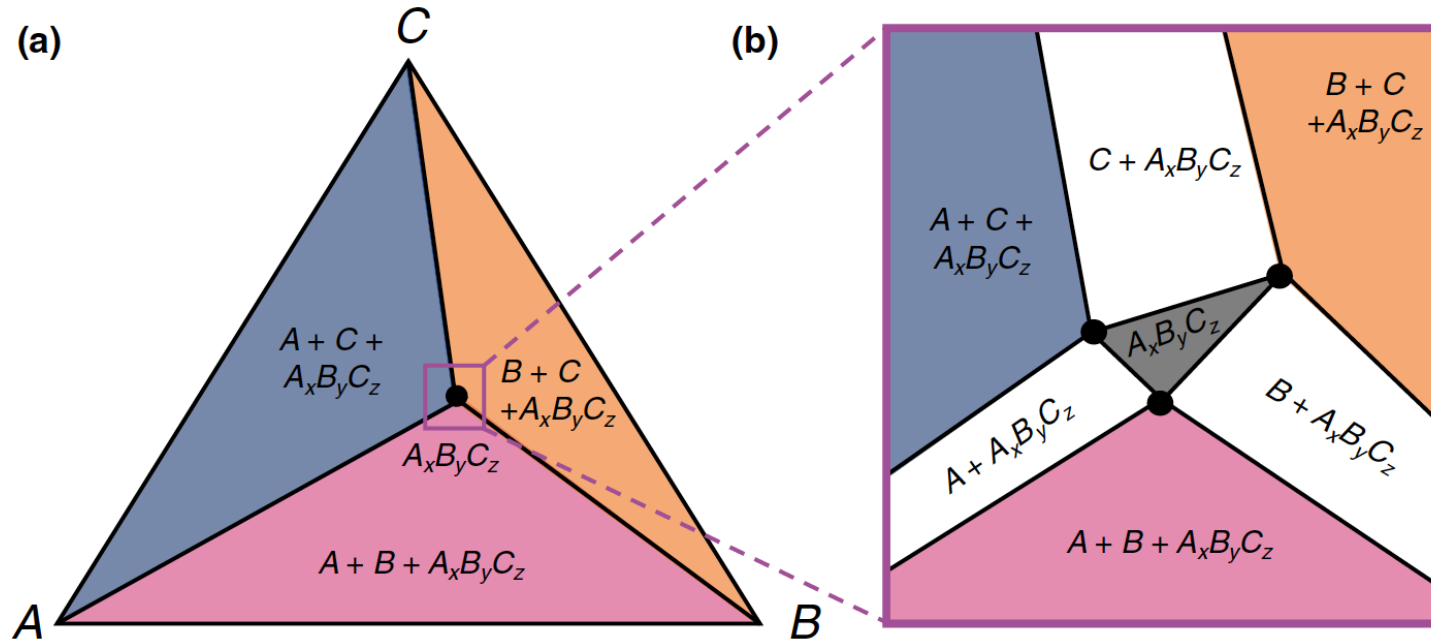
Adekoya, Snyder. *Advanced Functional Materials* 202403926 (2024)



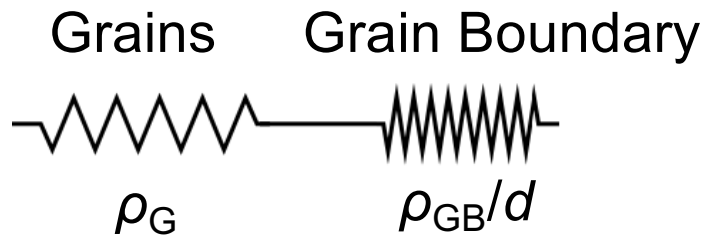
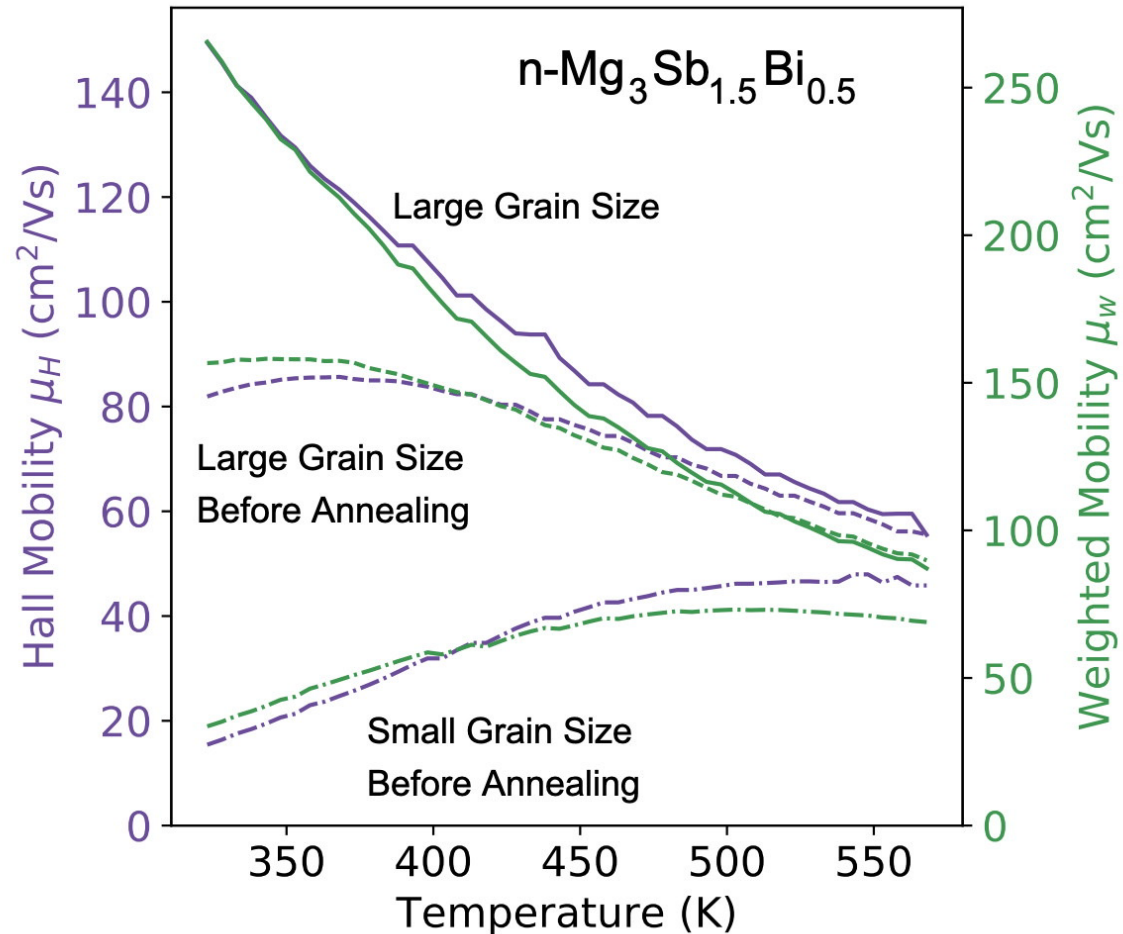
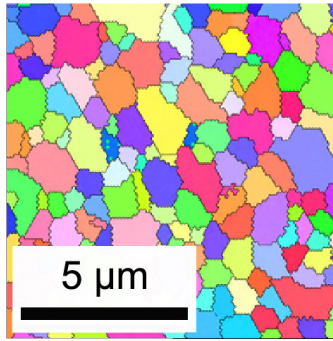
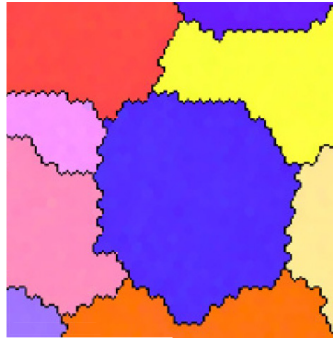
Thermoelectrics

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Phase Boundary Mapping



Grain Boundary Electrical Resistance



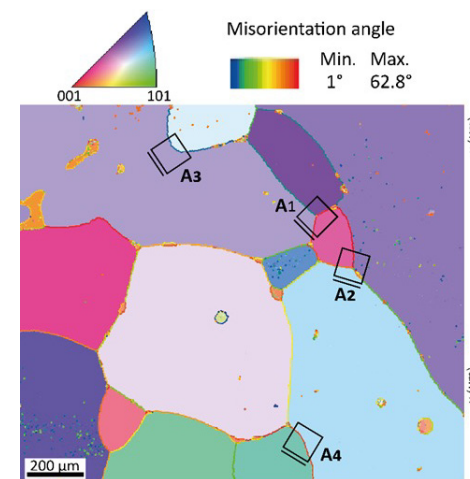
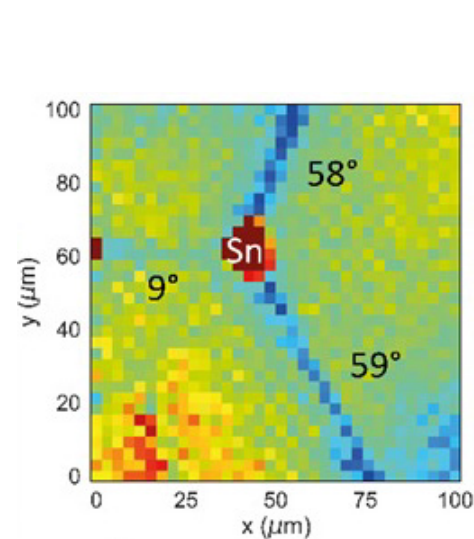
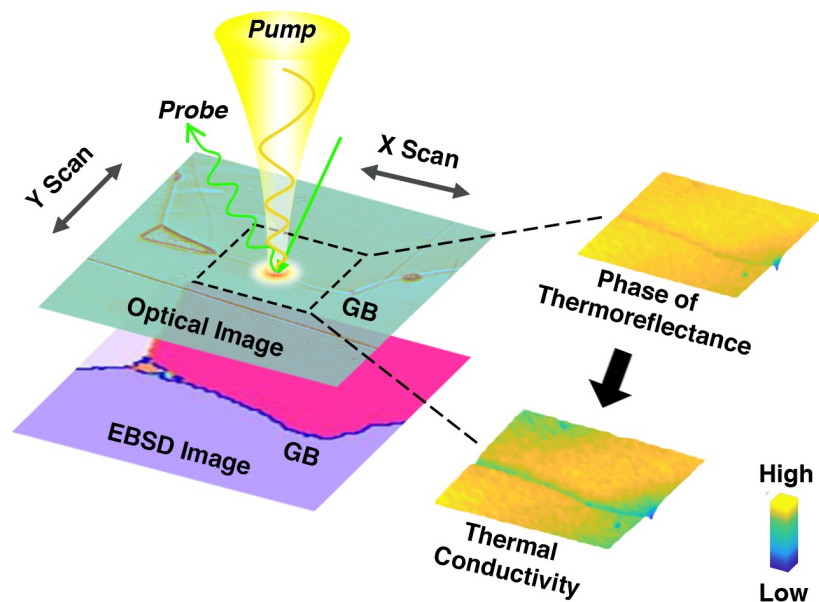
Kanno et. al., *Appl. Phys. Lett.* **112**, 033903 (2018)

J.J. Kuo, M. Wood, et al. *Energy Environ. Sci.* **13**, 1250 (2020)



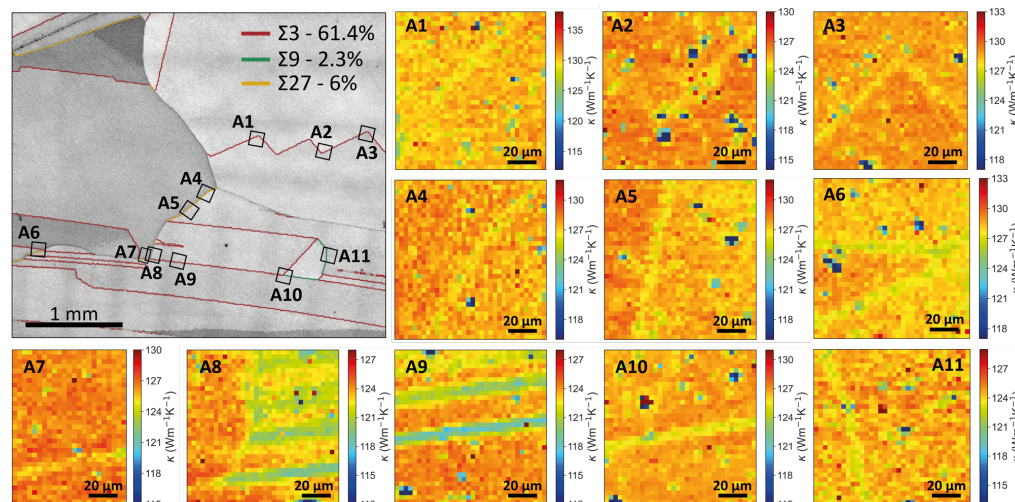
Scanning Thermal Images

SnTe



Si

Spatially-resolved frequency domain thermoreflectance (FDTR)



Homogeneous Assumption

Homogeneous Models

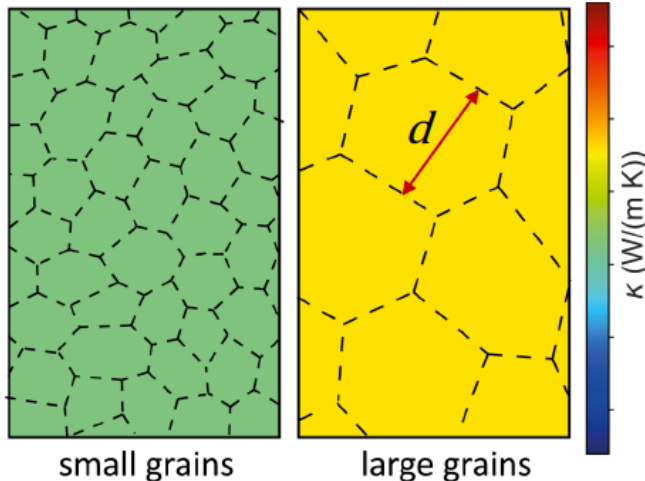
Klemens-Callaway

$$\kappa_l = \frac{1}{3} \int C_s(\omega) v_g^2(\omega) \tau(\omega) d\omega$$

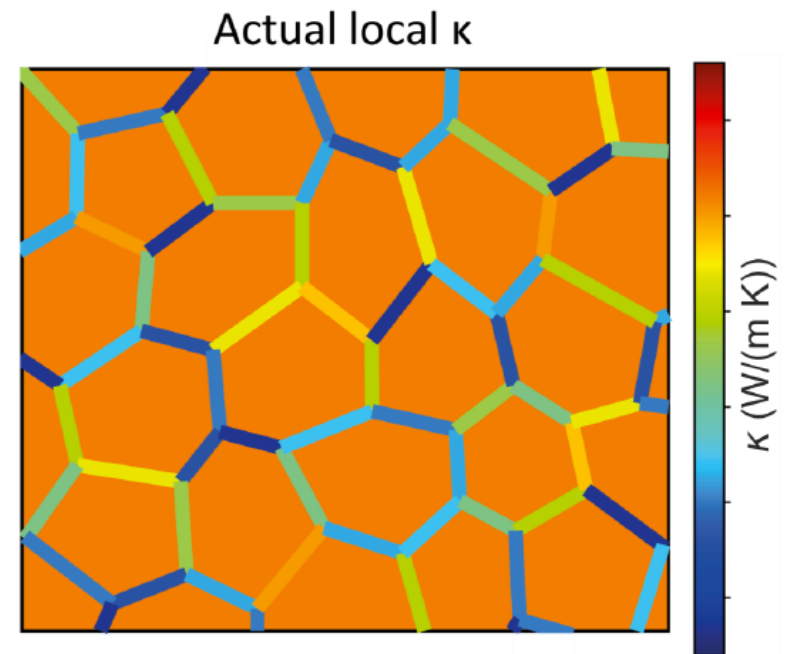
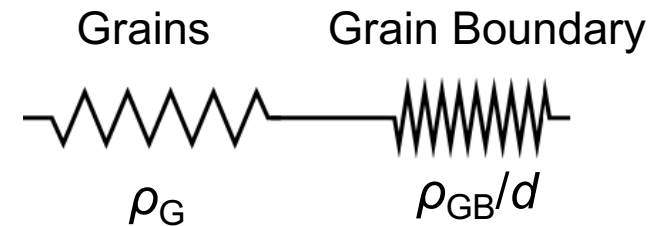
Lattice or Phonon thermal conductivity

$$\tau^{-1} = \frac{v}{d} + C_{DS} N_D B_D^2 \omega + C_U T \gamma^2 \omega^2 + C_{PD} \omega^4$$

↑ boundary
 ↑ dislocation
 ↑ Umklapp
 ↑ point defect



InHomogeneous Model

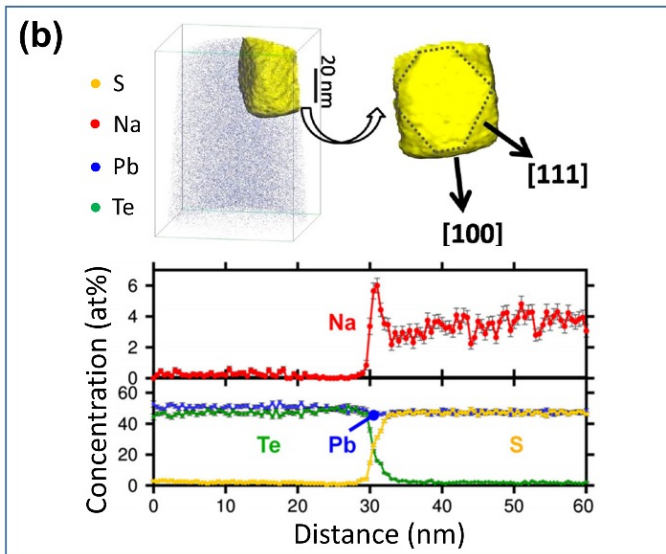
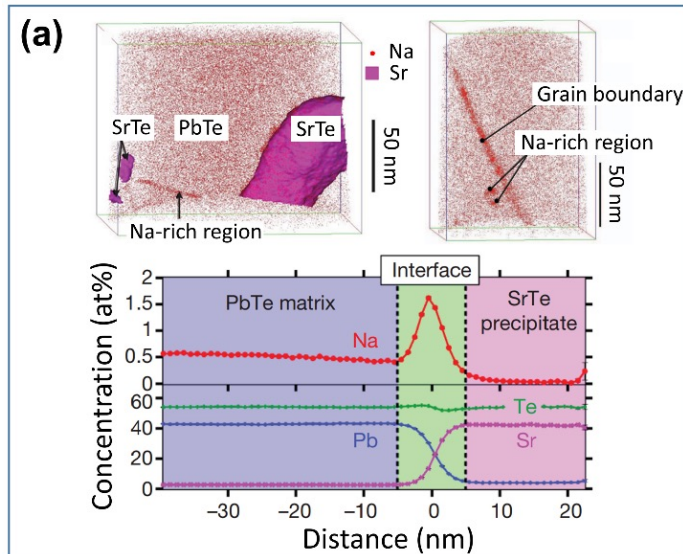


Interface Complexion Chemistry



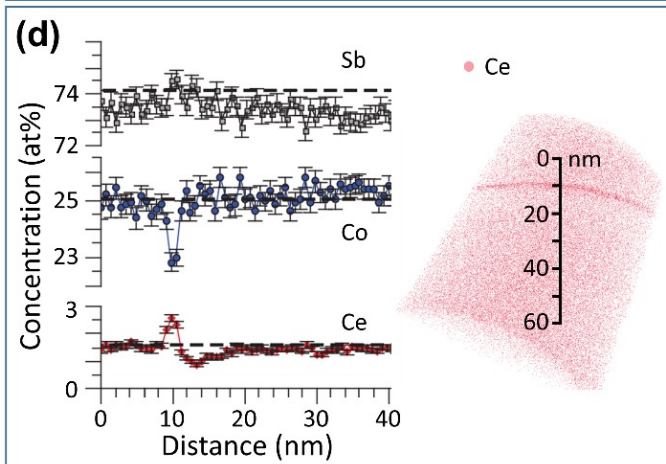
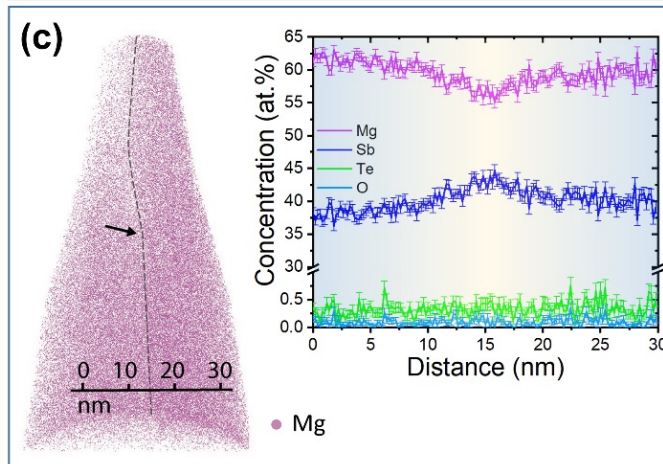
Atom Probe Tomography

(Pb,Sr,Na)Te



Pb(Te,S)

Mg₃Sb₂

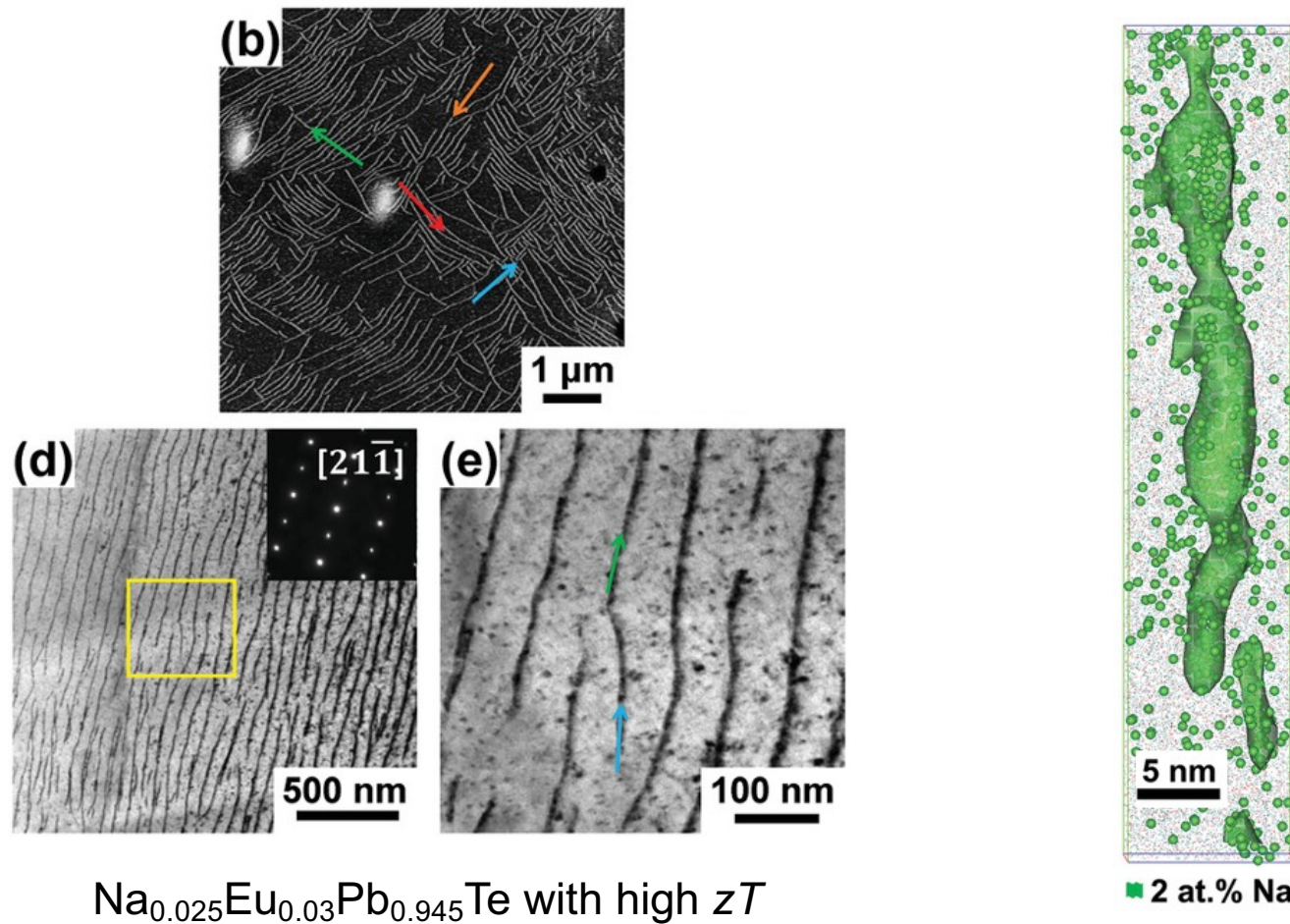


CeCo₄Sb₁₂

Parallel Dislocation Networks

Parallel dislocation networks at nanometer scale

Dislocations collect impurity dopant atoms = Cottrell atmosphere



Acknowledgements

Many Projects

Beautiful science in Complexity

Physics, Chemistry, Materials Science, Engineering

Thank you All!

Mentors

Group Members

Collaborators



Thermoelectrics

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